

# DS3170DK DS3/E3 Single-Chip Transceiver Design Kit

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## GENERAL DESCRIPTION

The DS3170DK is a fully integrated design kit for the DS3170 DS3/E3 single-chip transceiver (SCT). This design kit contains all the necessary circuitry to evaluate the DS3170 in all modes of operation. The design kit also includes an on-board microprocessor to run real-time code for further part evaluation.

## DESIGN KIT CONTENTS

DS3170DK Board

Download:

ChipView Software

DS3170DK.DEF Definition File

DS3170DK Data Sheet

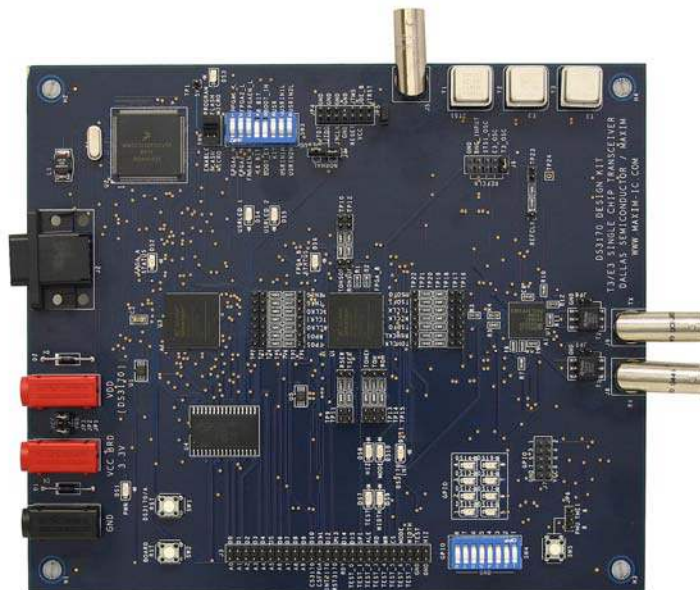
## ORDERING INFORMATION

PART	DESCRIPTION
DS3170DK	Design Kit for the DS3170 DS3/E3 Single-Chip Transceiver

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## FEATURES

- Expedites New Designs by Eliminating First-Pass Prototyping
- Demonstrates Key Functions of the DS3170 DS3/E3 Single-Chip Transceiver (SCT)
- Includes DS3170 Single-Chip Transceiver (SCT), Transformers, 75Ω BNC, and Termination Passives
- Interfaces with Any PC with an RS-232 Serial Interface
- High Level Windows®-Based Software Provides Visual Access to All Registers
- Software Controlled (Register) Mapped Configuration Switches Facilitate Real-Time Clock and Signal Routing
- Precision Test Points for All Clocks and Signals
- On-Board DS3 and E3 Crystal Oscillators for Stable Clock Generation
- Easy-to-Read Silkscreen Labels Identify the Signals Associated with All Connectors, Jumpers, and LEDs



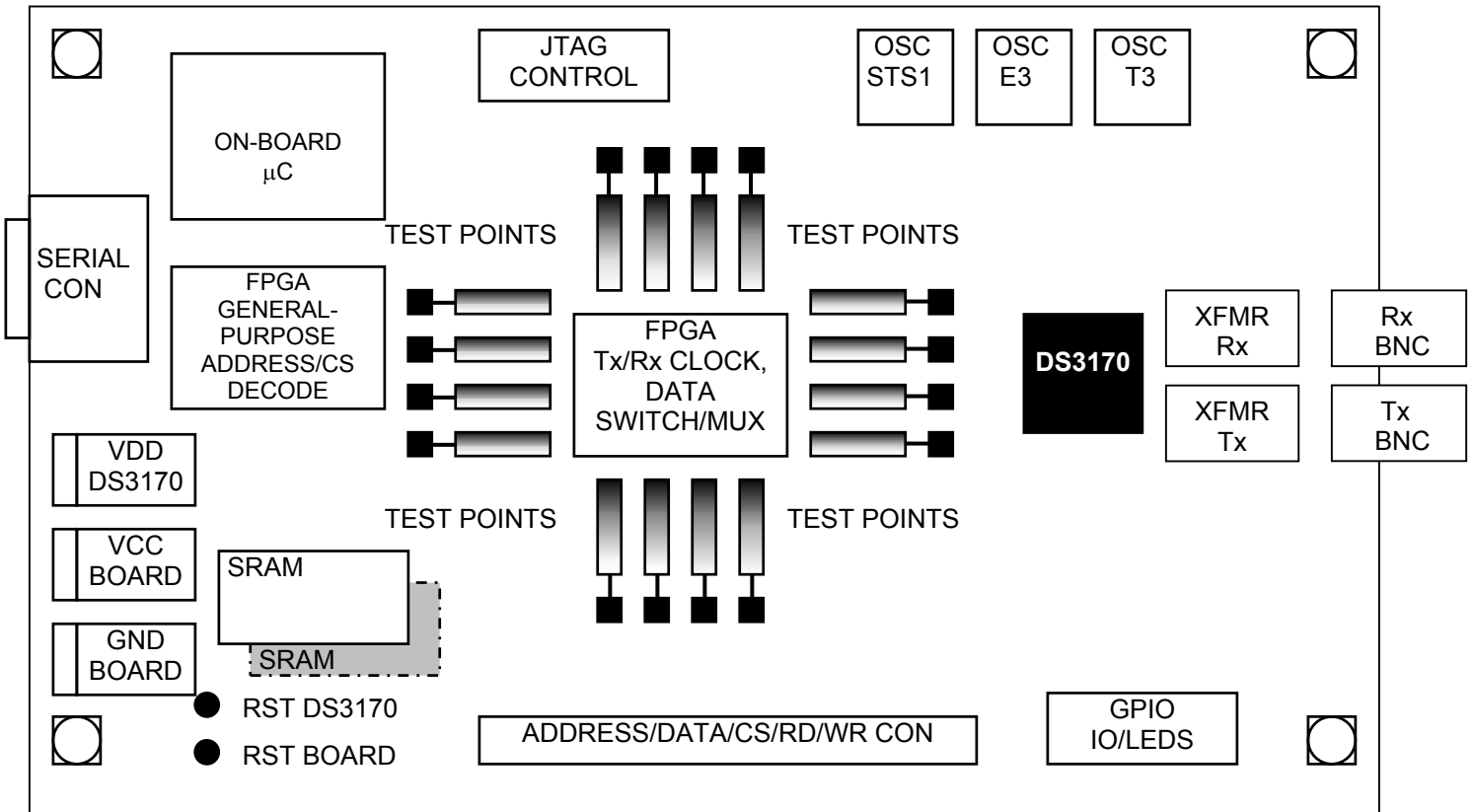
**COMPONENT LIST**

DESIGNATION	QTY	DESCRIPTION	SUPPLIER	PART NUMBER
C1, C4, C5, C10, C14, C15, C18, C19, C21, C24, C25–C32, C36–C38, C39–C44, C47–C49, C50, C52–C56, C59–C61, C66, C68, C70, C73, C74	44	0.1 $\mu$ F 20%, 16V X7R ceramic capacitors (0603)	AVX	0603YC104MAT
C2, C3, C16, C17, C20, C22, C23, C33, C34, C51, C57, C69, C75	13	1 $\mu$ F 10%, 16V ceramic capacitors (1206)	Panasonic	ECJ-3YB1C105K
C6, C62, C65	3	0.001 $\mu$ F 10%, 50V ceramic capacitors (0603)	Panasonic	ECJ-1VB1H102K
C7, C8, C9, C11, C35, C58, C76	7	68 $\mu$ F 20%, 16V tantalum capacitors (D case)	Panasonic	ECS-T1CD686R
C12, C13	2	10pF 5%, 50V ceramic capacitors (tall case)	Phycomp	1206CG100J9B200
C45, C46	2	10,000pF 10%, 16V ceramic capacitors (0603)	Panasonic	ECJ-1VB1C103K
C63, C64, C67	3	0.01 $\mu$ F 10%, 50V X7R ceramic capacitors (0603)	AVX	06035C103KAT
C71, C72	2	56,000pF 10%, 16V ceramic capacitors (0603)	Panasonic	ECJ-1VB1C563K
D1, D2	2	1A 50V general-purpose silicon diodes	General Semiconductor	1N4001
DS1, DS2, DS6–DS10	7	LED, green, SMD	Panasonic	LN1351C
DS3, DS4, DS5, DS11–DS19	12	LED, red, SMD	Panasonic	LN1251C
J1, PWR_CONNBAN1	2	Banana plug sockets (horizontal, black)	Mouser Electronics	164-6218
J2	1	DB9 right-angle connector (long case)	AMP	747459-1
J3	1	50-pin, dual-row, vertical terminal strip	Samtec	TSW-125-07-T-D
J4	1	100-mils 4-position jumper	Samtec	NA
J5	1	50 $\Omega$ BNC connector (5-pin right-angle header)	Trompeter	CBJR220
J6, J7	2	Terminal strip, 10-pin, dual row, vertical	Samtec	NA
J8, J9	2	75 $\Omega$ BNC connectors (5-pin right-angle)	Trompeter	UCBJR220
JP1, JP2, JP3, JP5, JP7, JP8	6	2-pin headers, 0.100" centerline (vertical)	Samtec	TSW-102-07-T-S
JP4	1	14-pin connector (dual row, vertical)	Samtec	NA
JP6	1	100-mils 3-position jumper	Samtec	NA
L1	1	1.0 $\mu$ H 20% 2-pin surface-mount inductor	Coiltronics	UP1B-1R0
PWR_CONNBAN2	1	Banana plug socket (horizontal, red)	Mouser Electronics	164-6219

DESIGNATION	QTY	DESCRIPTION	SUPPLIER	PART NUMBER
R1–R4, R12, R42, R43, R54–R56, R59, R63, R68, R69, R70, R73, R74, R83, R93, R107	20	150Ω 1%, 1/16W resistors (0603)	Panasonic	ERJ-3EKF1500V
R5–R8, R10, R15, R51, R57, R62, R71, R81, R85, R92, R94, R95, R100, R101, R103–R106, R109	22	33Ω 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ330V
R9, R11, R16, R22, R30, R32, R38, R46, R60, R61, R64, R65, R72, R77–R80, R89, R90, R91, R96	22	330Ω 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ331V
R13	1	1.0MΩ 5%, 1/16W resistor (0603)	Panasonic	ERJ-3GEYJ105V
R14, R17–R21, R23–R29, R31, R33–R37, R39, R40, R41, R44, R45, R47, R48, R49, R52, R53, R58, R67, R75, R76, R82, R86, R87, R98, R99, R102, R108, R110	41	10kΩ 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ103V
R50	1	1.0kΩ 5%, 1/16W resistor (0603)	Panasonic	ERJ-3GEYJ102V
R66, R88, R97	3	0Ω 1%, 1/16W resistors (0603)	AVX	CJ10-000F
R84	1	51.1Ω 1%, 1/16W resistor (0603)	Panasonic	ERJ-3EKF51R1V
SW1, SW2, SW5	3	4-pin single-pole switch MOM	Panasonic	EVQPAE04M
SW3, SW4	2	8-position switch, 16-pin DIP, low profile	AMP	435668-7
SW6	1	Slide switch (DPDT) 6-pin through-hole	Tyco	SSA22
T1, T2	2	1:2 XFMR T3/E3/STS-1 (industrial)	Pulse	T3012
TP1–TP24	24	Test points, compensated, 3pF, 953Ω, 3 plated holes	NA	KIT1
U1, U5	2	8-pin power-μMAX (1.8V or Adj)	Maxim	MAX1792EUA18
U2	1	M-CORE 32-bit microcontroller	Motorola	MMC2107
U3, U6	2	Spartan-II E 200K gate, 1.8V FPGA, 256 PIN BGA	Xilinx	XC2S200E-6FT256C
U4, U11	2	128K x 8 SRAM	Cypress	CY62128V
U7	1	DS3/E3 SCT 100-pin CSBGA (11mm x 11mm)	Dallas Semiconductor	DS3170
U8	1	3.3V RS-232 20-pin SO	Maxim	MAX3233EEWP
U9, U14, U16–U20, U23	8	High-speed buffer	Fairchild	NC7SZ86

DESIGNATION	QTY	DESCRIPTION	SUPPLIER	PART NUMBER
U10, U12	2	2Mb flash-based configuration memory	Xilinx	XCF02SV020C
U13	1	Quad 2-input NAND gate 14-pin SO	Toshiba	TC74HC00AFN
U15, U21, U24	3	Hex inverter, SO	Toshiba	TC74HC04AFN
U22	1	SOT switch debouncer	Maxim	MAX6816
X1	1	8.0MHz low-profile crystal	Dove Electronic	EC1-8.000M
Y1	1	3.3V 51.840MHz oscillator, crystal clock	SaRonix	NTH089AA3-51.840
Y2	1	3.3V 34.368MHz oscillator, crystal clock	SaRonix	NTH089AA3-34.368
Y3	1	3.3V 44.736MHz oscillator, crystal clock	SaRonix	NTH089AA3-44.736

### BOARD FLOORPLAN



## BASIC OPERATION

This design kit relies upon several supporting files, which are available for downloading on our website at [www.maxim-ic.com/telecom](http://www.maxim-ic.com/telecom). See the DS3170DK QuickView page for files.

The support files are used with an evaluation program called ChipView with is available for download at [www.maxim-ic.com/telecom](http://www.maxim-ic.com/telecom).

## HARDWARE CONFIGURATION

### Quick Start (Hardware Settings)

- For single power-supply operation, short jumpers JP1-JP3. This connects VDD of the DS3170 to the board VCC.
- Ensure that *PROGRAM FLASH MICRO* is selected (SW6). DS3 should not be on.
- Connect reference clock. See [Table 1](#).
- DIP switches (SW3) can be in either the ON or OFF position depending on the desired configuration. See [Table 6](#).
- Connect serial cable from DS3170DK (J2) to PC.
- Supply 3.3V to the banana-plug receptacles marked GND and VCC\_3.3V.

### Reference Clock Configuration

The reference clock for the DS3170 (SCT) can be configured a number of ways depending on the application's need. This is done by shorting the REFCLK signal on J6 to the signal inputs, which are also connected to J6.

**Table 1: Reference Clock Configuration**

REFERENCE CLOCK	DESCRIPTION
GND	Short pins J6.1 and J6.2 together. Open all other pins on J6.
BNC Input	Short pins J6.3 and J6.4 together. Open all other pins on J6.
STS1 OSC	Short pins J6.5 and J6.6 together. Open all other pins on J6.
E3 OSC	Short pins J6.7 and J6.8 together. Open all other pins on J6.
T3 OSC	Short pins J6.9 and J6.10 together. Open all other pins on J6.

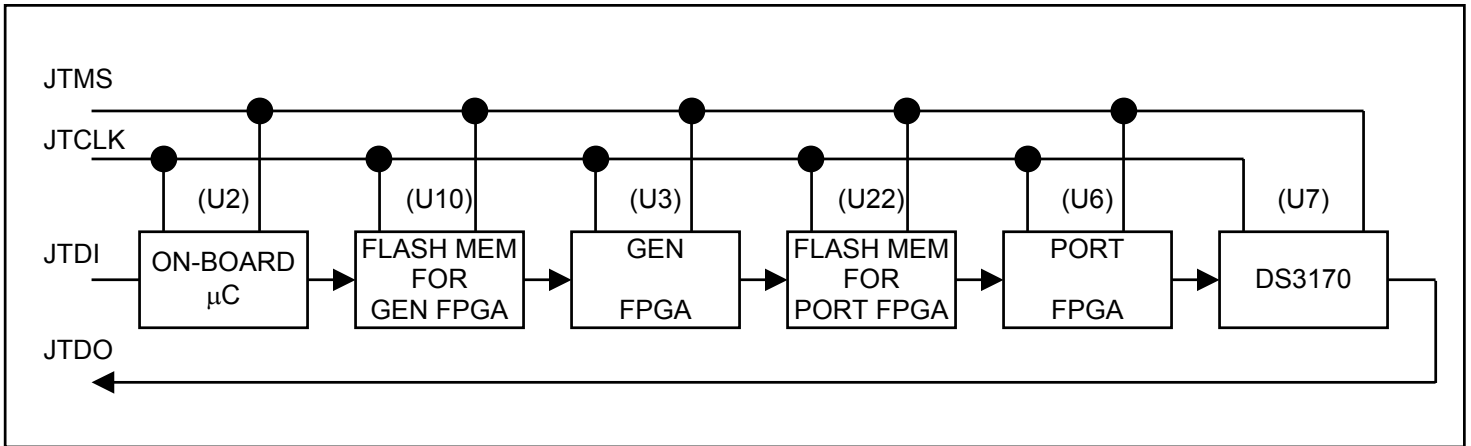
### JTAG Configuration

The JTAG chain is controlled by the following connectors: J4, JP4, and JP5. Depending on the function, such as programming the internal microcontroller flash or performing boundary scan operations, the three connectors can be configured to accomplish the desired task. For information on programming the internal flash of the microcontroller, refer to the microcontroller user manual and board schematic.

For most purposes, having the complete JTAG chain is sufficient. [Figure 1](#) shows the complete chain as well as what order the devices will appear during boundary scan. To set up this configuration, perform the following:

- Connect JTDI to JP4.1
- Connect JTDO to JP4.3
- Connect JTMS to JP4.10
- Connect JCLK to JP4.5
- Connect J4.1 to J4.2
- Connect J4.3 to J4.4
- Connect JP5.1 to JP5.2

**Figure 1. JTAG Chain**



**Address/Data BUS Connector**

The DS3170DK has a connector (J3) to monitor all local bus activity for the design kit. All the signals can be captured with a high-impedance probe and displayed on an oscilloscope or logic analyzer. **Note:** If FPGA\_ENABLE (SW3.3) is logic 0, the on-board microcontroller will no longer drive any data onto the local bus. Therefore, the user can now connect the local bus of the DS3170 into another system without making any modifications to the hardware. See [Table 2](#) for specific pin information for connector J3.

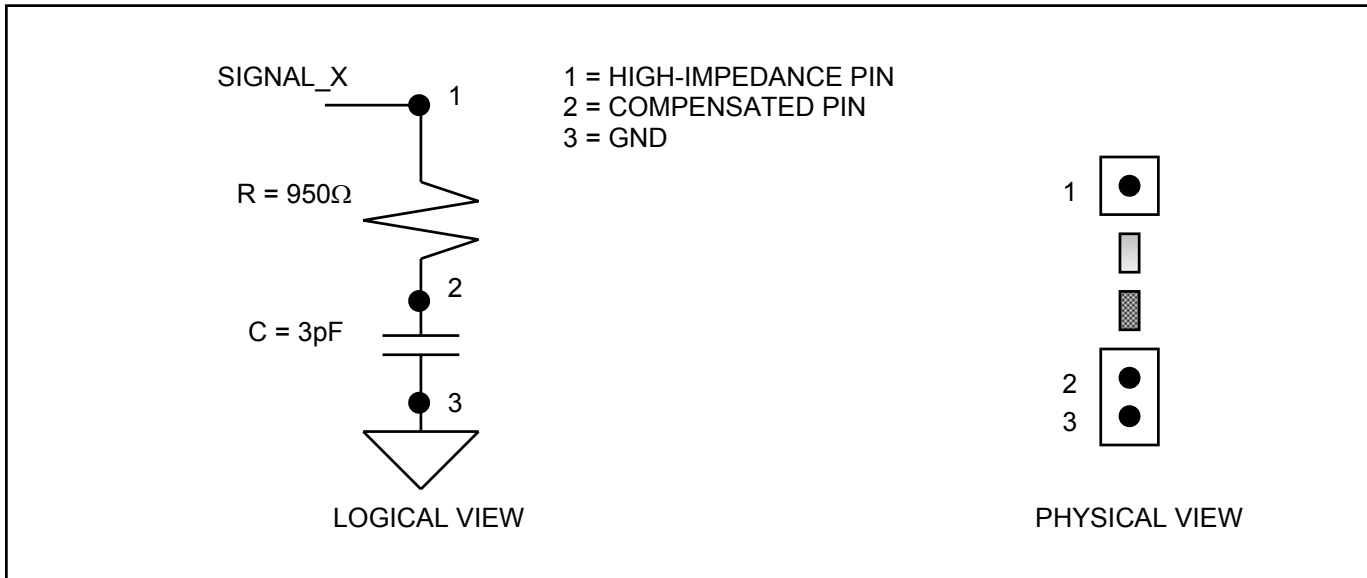
**Table 2. Address/Data Connector**

PIN NUM	PIN NAME	DESCRIPTION	PIN NUM	PIN NAME	DESCRIPTION
1	A0	Local Address Bit 0	2	D0	Local Data Bit 0
3	A1	Local Address Bit 1	4	D1	Local Data Bit 1
5	A2	Local Address Bit 2	6	D2	Local Data Bit 2
7	A3	Local Address Bit 3	8	D3	Local Data Bit 3
9	A4	Local Address Bit 4	10	D4	Local Data Bit 4
11	A5	Local Address Bit 5	12	D5	Local Data Bit 5
13	A6	Local Address Bit 6	14	D6	Local Data Bit 6
15	A7	Local Address Bit 7	16	D7	Local Data Bit 7
17	A8	Local Address Bit 8	18	D8	Local Data Bit 8
19	A9	Local Address Bit 9	20	D9	Local Data Bit 9
21	CS3170	Chip Select DS3170	22	D10	Local Data Bit 10
23	CSFPGA	Chip Select Port FPGA	24	D11	Local Data Bit 11
25	INT3170	INT PIN DS3170	26	D12	Local Data Bit 12
27	RST3170	RST PIN DS3170	28	D13	Local Data Bit 13
29	RDY	Ready Handshake DS3170	30	D14	Local Data Bit 14
31	TEST0	Generic I/O Bit 0	32	D15	Local Data Bit 15
33	TEST1	Generic I/O Bit 1	34	SPI	DS3170 Serial/Parallel Bus Mode
35	TEST2	Generic I/O Bit 2	36	ALE	Address Latch Enable
37	TEST3	Generic I/O Bit 3	38	RD_DS	Read (Intel)/Data Strobe (MOT)
39	TEST4	Generic I/O Bit 4	40	WR_W/R	Write (Intel)/Write_READ (MOT)
41	TEST5	Generic I/O Bit 5	42	CS_OUT	Programmable CS_OUT Pin
43	TEST6	Generic I/O Bit 6	44	MODE	Mot/Intel Mode
45	TEST7	Generic I/O Bit 7	46	WIDTH	Data Bus Width
47	GND	GND	48	TEST	Test Enable (Active Low)
49	GND	GND	50	HIZ	High Impedance (Active Low)

## High Impedance and Compensated Test Points

The test points for all the clock and data lines are unique for this board such that each test point listed in [Table 3](#) have a relative high-impedance pin and a compensated pin. The compensated pin is part of a (20:1) voltage divider that when used with the standard  $50\Omega$  load of an oscilloscope provides a very clean signal. If you are making critical timing and or slew rate measurements, the compensated test points are very useful. [Figure 2](#) shows the relationship between the high-impedance and compensated test point pins.

**Figure 2. Test Point Logical and Physical View**



**Table 3. Test Points**

REF DES	SIGNAL NAME	REF DES	SIGNAL NAME
TP5	TCLKI	TP7	TNEG
TP6	TCLKO	TP8	RNEG
TP4	RCLKO	TP2	TPOS
TP20	TLCLK	TP3	RPOS
TP19	RLCLK	TP11	TSER
TP10	TOHSOF	TP9	RSER
TP12	ROHSOF	TP13	TOHEN
TP16	TOHCLK	TP14	TOH
TP17	ROHCLK	TP15	ROH
TP19	TSOFO	TP23	REFCLK
TP22	RSOFO	TP21	TSOFI

## General Purpose Input/Output for DS3170

The DS3170 SCT has an 8-bit port that can be bit configured as either general-purpose I/O or specific alarms, a TEMI input, or PMU input. Refer to the DS3170 data sheet for specific questions about the operation of the DS3170 GPIO port.

Each GPIO pin has two types of inputs and an LED for easy identification of the pin's state. The first input type for the GPIO port is an 8-bit switch (SW4). Each pin on SW4 corresponds to the bit in the GPIO. When the switch is in the "On" position, the pin for the switch is grounded and provides logic 0 to the port. When the switch is in the "Off" position, the pin for the switch floats to VDD and provides logic 1 to the port.

The second input type for the GPIO port is a straight 10-pin header (J7). This can be simply a monitoring pin for the GPIO port or used as input stimulus. **Note:** If you plan to drive a bit to a value other than GND, the GPIO bit in SW4 must be in the "Off" position. See the DS3170DK schematic for questions on the connection of the GPIO port.

[Table 4](#) provides a description of pin out of SW4 and J7.

**Table 4. GPIO Header and Switch Pinout**

PIN NUMBER		PIN NAME
SW4.1	J7.1	GPIO Bit 1
SW4.2	J7.2	GPIO Bit 2
SW4.3	J7.3	GPIO Bit 3
SW4.4	J7.4	GPIO Bit 4
SW4.5	J7.5	GPIO Bit 5
SW4.6	J7.6	GPIO Bit 6
SW4.7	J7.7	GPIO Bit 7
SW4.8	J7.8	GPIO Bit 8

## TEMI and PMU Inputs

GPIO Bit 6 and GPIO Bit 8 can be configured to be the TEMI and PMU inputs respectively. A pushbutton (SW5) and 3-position jumper (JP6) are available to provide a glitch-free input to either of these inputs. **Note:** When using the pushbutton (SW5) and 3-position jumper (JP6) as an input to the GPIO pins, you must have the appropriate switch in SW4 in the "Off" position.

**Table 5. TEMI and PMU Configuration**

SIGNAL NAME	SETUP PROCEDURE
TEMI	Set SW4.6 to the "Off" position
	Short (Jumper) JP6.3 and JP2
PMU	Set SW4.8 to the "Off" position
	Short (Jumper) JP6.1 and JP2



## User Input Switch (SW3)

SW3 is an 8-pin DIP switch that controls the function of the on-board microcontroller and the two on-board FPGAs, and offers a number of generic inputs for user programs.

**Table 6. User Input Switch Pinout**

PIN	NAME	FUNCTION
1	FPGA INPUT 1	Generic Input-Only Pin to the General-Purpose FPGA. Value of pin is copied to general-purpose register XXXXXXXX. Can be used for user programs. This pin has no effect if FPGA ENABLE is logic 0.
2	FPGA INPUT 2	Generic Input-Only Pin to the General-Purpose FPGA. Value of pin is copied to general-purpose register XXXXXXXX. Can be used for user programs. This pin has no effect if FPGA ENABLE is logic 0.
3	FPGA ENABLE	Input-Only Pin to the General-Purpose FPGA (U3). When this pin is logic 1 (SW3.3 is OFF), the FPGA is enabled and will transfer data from the DS3170 and FPGA as directed from the on-board microcontroller. When this pin is logic 0 (SW3.3 is ON), the FPGA is disabled. All inputs and outputs to the DS3170 and port FPGA are tri-stated. <b>Note:</b> This pin does not cause a hardware enable for the PORT FGPA.
4	DATA BUS SELECT	Input-Only Pin to the General-Purpose FPGA (U3). When this pin is logic 1 (SW3.4 is OFF), the DS3170 and the port FPGA are set up such that they use the 16-bit bus from the on-board microcontroller. When this pin is logic 0 (SW3.4 is ON), the DS3170 and the port FPGA are set up such that they use the 8-bit bus from the on-board microcontroller. This pin has no effect if FPGA ENABLE is logic 0.
5	BOOT SEL	Input-Only Pin to the On-Board Microcontroller. When this pin is logic 1 (SW3.5 is OFF), the on-board microcontroller loads the firmware from an external source rather than the internal flash bank. When this pin is logic 0 (SW3.5 is ON), the microcontroller loads the firmware from the internal flash bank. If you choose to load code from an external source, refer to the user manual for the on-board microcontroller (U2) to ensure that all the timing and data are correct to run this program. This option should only be used by the advanced user.
6	KIT	Input-Only Pin to the On-Board Microcontroller. Not implemented with the firmware shipped from Dallas Semiconductor. This pin can be used by a user program.
7	USER INPUT 1	Input/Output Pin to the General-Purpose FPGA (U3). This pin has an LED (DS4) to track the value of this signal. This pin has no effect if FPGA ENABLE is logic 0. <b>Note:</b> If you choose to use this as an output, USER INPUT 1 (SW3.7) must be in the off position.
8	USER INPUT 2	Input/Output Pin to the General-Purpose FPGA (U3). This pin has an LED (DS5) to track the value of this signal. This pin has no effect if FPGA ENABLE is logic 0. <b>Note:</b> If you choose to use this as an output, USER INPUT 1 (SW3.8) must be in the off position.

## SOFTWARE CONFIGURATION

### Quick Start (Software—ChipView)

- Perform steps in the Quick Start (Hardware Settings).
- Load ChipView software.
- Select COM port.
- Select Register View.
- From the Programs menu, launch the host application named ChipView.EXE. If the default installation options were used, click the Start button on the Windows toolbar and select Programs → ChipView → ChipView.
- Load the DS3170DK.DEF file.
- Make sure that all the register settings are correct for the proper function desired for the DS3170DK.
- Refer to the DS3170 data sheet for all questions pertaining to device functionality.

## MEMORY MAP

The on-board microcontroller is configured to start the user address space at 0x81000000. All offsets given in [Table 7](#) are relative to the beginning of the user address space. All device registers can be easily modified using ChipView.EXE host-based user-interface software.

**Table 7. Relative Address Map**

REF DES	DEVICE	OFFSET
U3	General-purpose FPGA	0x0000
U6	FPGA Tx/Rx clock, data switch/mux	0x1000
U7	DS3170 DS3/E3 single-chip transceiver	0x2000

**Table 8. General-Purpose Memory Map**

OFFSET	REGISTER NAME	TYPE	DESCRIPTION
0x00	BRDID	Read Only	Board ID
0x02	DSIDH	Read Only	Dallas Extended ID Upper Nibble
0x03	DSIDM	Read Only	Dallas Extended ID Middle Nibble
0x04	DSIDL	Read Only	Dallas Extended ID Lower Nibble
0x05	BRDREV	Read Only	Board Rev
0x06	ASMREV	Read Only	Assembly Rev
0x07	FPGAREV	Read Only	FPGA Firmware Rev
0x08	CTRL1	Control	Control Reg #1

## ID REGISTERS

### BID: BOARD ID (Offset=0X0000)

BID is read only with a value of 0xD.

### XBIDH: HIGH NIBBLE EXTENDED BOARD ID (Offset=0X0002)

XBIDH is read only with a value of 0x00.

### XBIDM: MIDDLE NIBBLE EXTENDED BOARD ID (Offset=0X0003)

XBIDM is read only with a value of 0x07.

### XBIDL: LOW NIBBLE EXTENDED BOARD ID (Offset=0X0004)

XBIDL is read only with a value of 0x00.

### BREV: BOARD FAB REVISION (Offset=0X0005)

BREV is read only and displays the current fab revision.

### AREV: BOARD ASSEMBLY REVISION (Offset=0X0006)

AREV is read only and displays the current assembly revision.

### PREV: PLD REVISION (Offset=0X0007)

PREV is read only and displays the current PLD firmware revision.

## CONTROL REGISTERS

Register Name: **CTRL1**

Register Description: **Control Register 1**

Register Offset: **0x0008**

Bit #	7	6	5	4	3	2	1	0
Name	SPI_CPOL	SPI_CPHA	SPI_SWAP	SPI	HIZ	WIDTH	MOT	MUX
Default	0	0	0	0	1	0	0	0

**Bit 7: SPI\_CPOL:** This bit controls the SPI Interface Clock Polarity pin, which is muxed with the D7 pin on the DS3170. Bit 7 is only active when bit 4 (SPI) is a logic 1. Refer to the DS3170 data sheet for pin operation.

**Bit 6: SPI\_CPHA:** This bit controls the SPI Interface Clock Phase pin, which is muxed with the D6 pin on the DS3170. Bit 6 is only active when Bit 4 (SPI) is a logic 1. Refer to the DS3170 data sheet for pin operation.

**Bit 5: SPI\_SWAP:** This bit controls the SPI Interface Bit Order Swap pin, which is muxed with the D5 pin on the DS3170. Bit 5 is only active when Bit 4 (SPI) is a logic 1. Refer to the DS3170 data sheet for pin operation.

**Bit 4: SPI:** This bit controls the SPI Bus Mode bit.  
0 = parallel bus mode  
1 = SPI bus mode

**Bit 3: HIZ:** This bit controls the high-impedance test-enable bit (active low). This signal puts all the digital outputs and bidirectional outputs to a high-impedance state when pulled low and also when the JTRST is pulled low. For normal operation, keep it as a logic 1.

**Bit 2: WIDTH:** This bit controls the databus width pin for parallel bus mode.  
0 = 8-bit parallel mode  
1 = 16-bit parallel mode

**Bit 1: MOT:** This bit controls the MODE pin for the DS3170.  
0 = RD/WR strobe mode (Intel)  
1 = DS strobe mode (Motorola)

**Bit 0: MUX:** This bit determines if the ALE pin on the DS3170 is in mux mode or nonmux mode (constantly high).  
0 = nonmux mode  
1 = mux mode

Register Name: **CTRL2**Register Description: **Control Register 2–Line IO**Register Offset: **0x0009**

Bit #	7	6	5	4	3	2	1	0
Name	RNEG3	RNEG2	RNEG1	RNEG0	RPOS3	RPOS2	RPOS1	RPOS0
Default	0	0	0	0	1	0	0	0

**Bits 7 to 4: RNEGx:** These bits control the source of the RNEG signal.**Bits 3 to 0: RPOSx:** These bits control the source of the RPOS signal.

RPOSx	DESCRIPTION
0x00	HI-Z
0x01	TPOS
0x02	T3 OSC
0x03	E3 OSC
0x04	STS1 OSC
0x05	BNC_INPUT
0x06	Logic 0
0x07	Logic 1
0x08–0xFF	HI-Z

RNEGx	DESCRIPTION
0X00	HI-Z
0X01	TNEG
0X02	T3 OSC
0X03	E3 OSC
0X04	STS1 OSC
0X05	BNC_INPUT
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

Register Name: **CTRL3**Register Description: **Control Register 3–Line RCLK**Register Offset: **0x000A**

Bit #	7	6	5	4	3	2	1	0
Name	—	—	—	—	RLCLK3	RLCLK2	RLCLK1	RLCLK0
Default	0	0	0	0	0	0	0	0

**Bits 7 to 4:** These bits are unused.**Bits 3 to 0: RLCLKx:** These bits control the source of the RLCLK signal.

RLCLKx	DESCRIPTION
0X00	HI-Z
0X01	TLCLK
0X02	T3 OSC
0X03	E3 OSC
0X04	STS1 OSC
0X05	BNC_INPUT
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

Register Name: **CTRL4**Register Description: **Control Register 4 Overhead Interface**Register Offset: **0x000B**

Bit #	7	6	5	4	3	2	1	0
Name	TOHEN3	TOHEN2	TOHEN1	TOHEN0	TOH3	TOH2	TOH1	TOH0
Default	0	0	0	0	0	0	0	0

**Bits 7 to 4: TOHENx:** These bits control the source of the TOHEN signal.**Bits 3 to 0: TOHx:** These bits control the source of the TOH signal.

TOHENx	DESCRIPTION
0X00	HI-Z
0X01	TOHSOF
0X02	ROHSOF
0X03	Not used
0X04	Not used
0X05	Not used
0X06	Logic 0
0X07	Logic 1
0X08-0XFF	HI-Z

TOHx	DESCRIPTION
0X00	HI-Z
0X01	ROH
0X02	Not used
0X03	Not used
0X04	Not used
0X05	Not used
0X06	Logic 0
0X07	Logic 1
0X08-0XFF	HI-Z

Register Name: **CTRL5**Register Description: **Control Register 5 Serial Data Overhead Interface**Register Offset: **0x000C**

Bit #	7	6	5	4	3	2	1	0
Name	—	—	—	—	TSER3	TSER2	TSER1	TSER0
Default	0	0	0	0	0	0	0	0

**Bits 7 to 4:** These bits are unused.**Bits 3 to 0: TSERx:** These bits control the source of the TSER signal.

<b>TSERx</b>	<b>DESCRIPTION</b>
0X00	HI-Z
0X01	RSER
0X02	Not Used
0X03	Not Used
0X04	Not Used
0X05	Not Used
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

Register Name: **CTRL6**Register Description: **Control Register 6 Serial Data Overhead Interface**Register Offset: **0x000D**

Bit #	7	6	5	4	3	2	1	0
Name	TSOFI3	TSOFI2	TSOFI1	TSOFI0	TCLKI3	TCLKI2	TCLKI1	TCLKI0
Default	0	0	0	0	0	0	0	0

**Bits 7 to 4: TSOFIx:** These bits control the source of the TSOFI signal.**Bits 3 to 0: TCLKIx:** These bits control the source of the TCLKI signal.

<b>TSOFIx</b>	<b>DESCRIPTION</b>
0X00	HI-Z
0X01	TSOFO
0X02	RSOFO
0X03	Not Used
0X04	Not Used
0X05	Not Used
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

<b>TCLKIx</b>	<b>DESCRIPTION</b>
0X00	HI-Z
0X01	TCLKO
0X02	RCLKO
0X03	Not Used
0X04	Not Used
0X05	Not Used
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z



## DS3170 INFORMATION

For more information about the DS3170, refer to the DS3170 data sheet available on our website at [www.maxim-ic.com/DS3170](http://www.maxim-ic.com/DS3170). Software downloads are also available for this design kit.

## DS3170DK INFORMATION

For more information about the DS3170DK including software downloads, consult the DS3170DK data sheet available on our website at [www.maxim-ic.com/DS3170DK](http://www.maxim-ic.com/DS3170DK).

## TECHNICAL SUPPORT

For additional technical support, e-mail your questions to [telecom.support@dalsemi.com](mailto:telecom.support@dalsemi.com).

## SCHEMATICS

The DS3170DK schematics are featured in the following 23 pages.

DS3170 DESIGN KIT

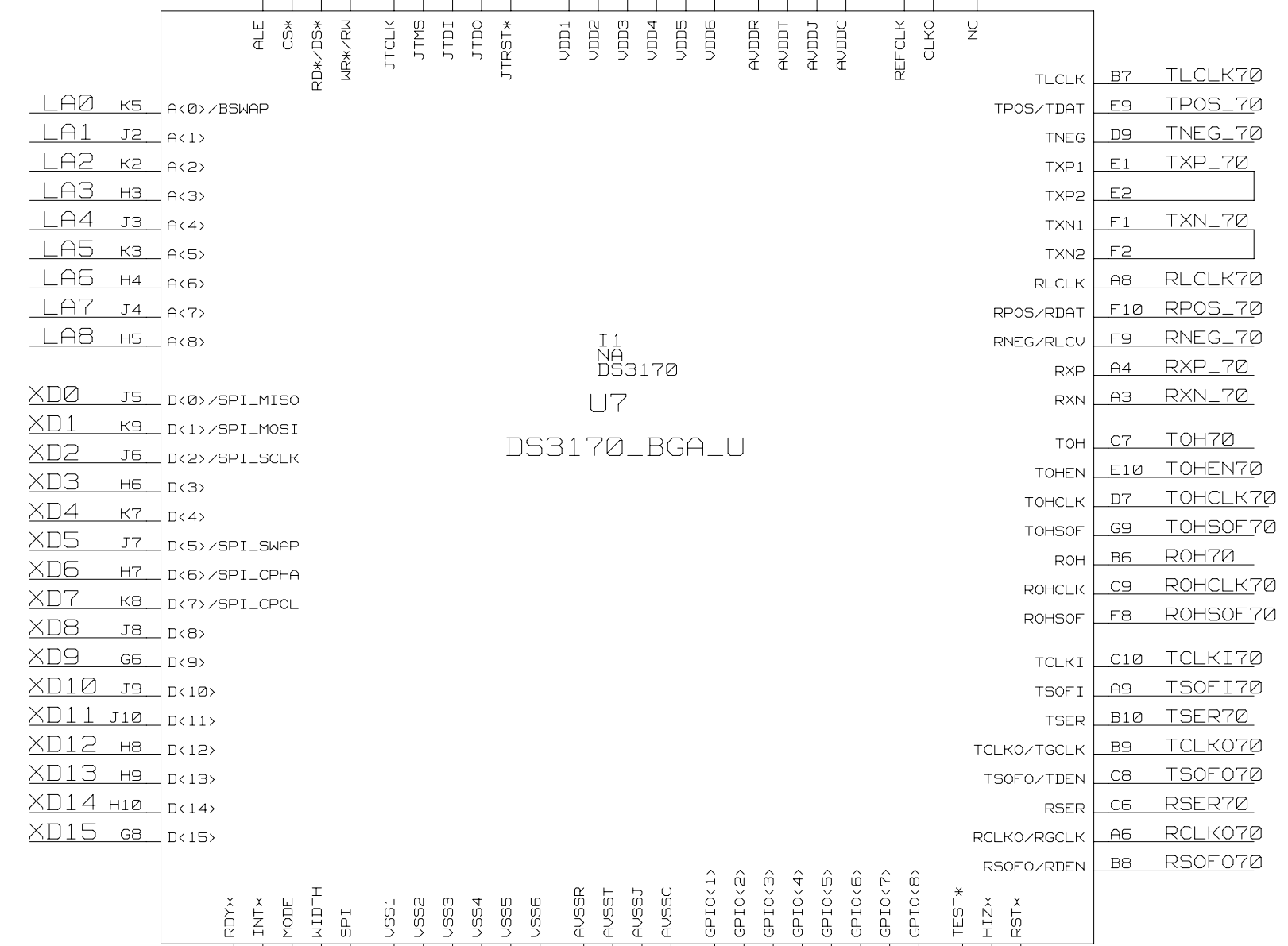
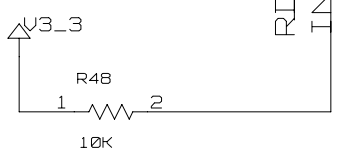
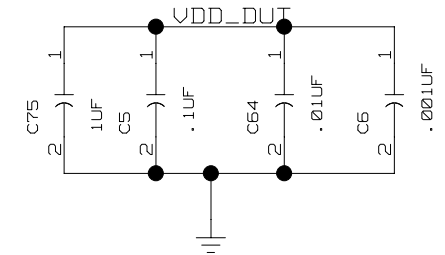
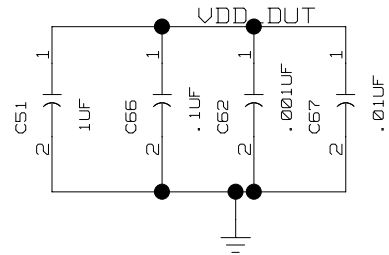
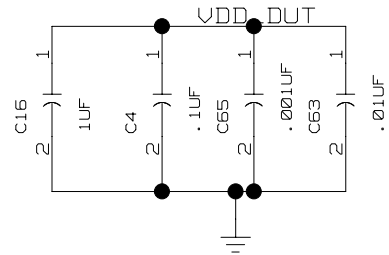
CREATED BY  
DALLAS SEMICONDUCTOR  
JUNE 26, 2004

Page 1.	COVER PAGE	Page 11.	MICROCONTROLLER BLOCK1
Page 2.	DS3170 BGA	Page 12.	MICROCONTROLLER BLOCK2
Page 3.	LIU INTERFACE	Page 13.	SERIAL/JTAG CONN
Page 4.	TCLK/RCLK/TELECOM DATA	Page 14.	MISC USER INPUTS
Page 5.	DS3170 RESET / GPIO	Page 15.	GP FPGA CONTROL / FLASH
Page 6.	MISC TELECOM SIGNALS	Page 16.	GP FPGA BLOCK1
Page 7.	REF OSC	Page 17.	GP FPGA BLOCK2
Page 8.	PORT FPGA CONTROL / FLASH	Page 18.	ADDRESS/DATA HEADERS
Page 9.	PORT FPGA BLOCK1	Page 19.	MICROCONTROLLER SRAM
Page 10.	PORT FPGA BLOCK2	Page 20.	POWER CONN
		Page 21.	NOTES

Fri Mar 18 13:45:59 2005

TITLE: Page 1. COVER PAGE	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 1

DS3170  
100 PIN BGA



Fri Mar 18 13:46:03 2005

TITLE: Page 2. DS3170 BGA	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 2

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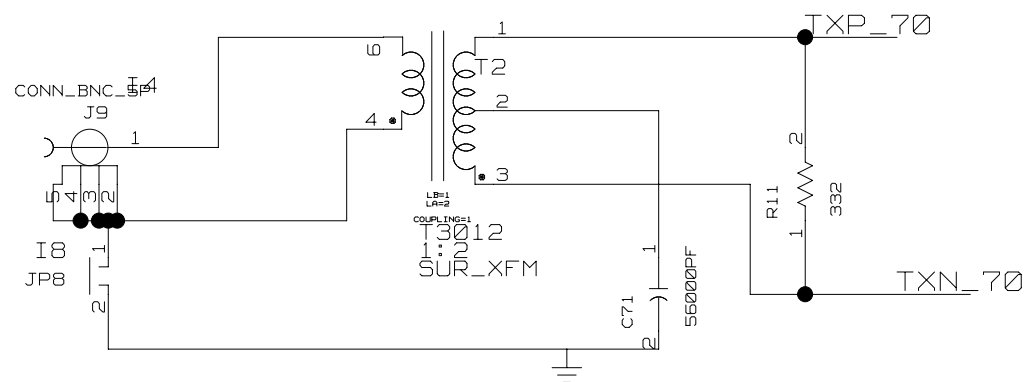
B

A

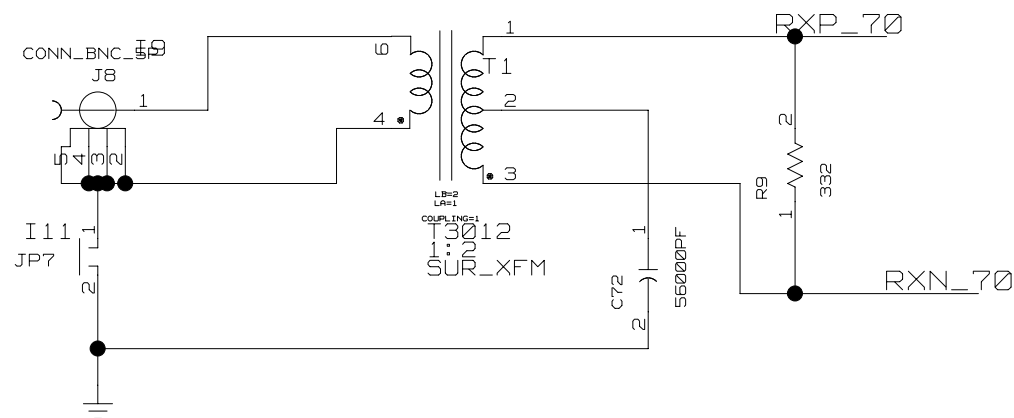
A

DS3170  
 100 PIN BGA  
 LIU INTERFACE

TRANSMIT



RECEIVE



Fri Mar 18 13:46:04 2005

TITLE: Page 3. LIU INTERFACE	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 3

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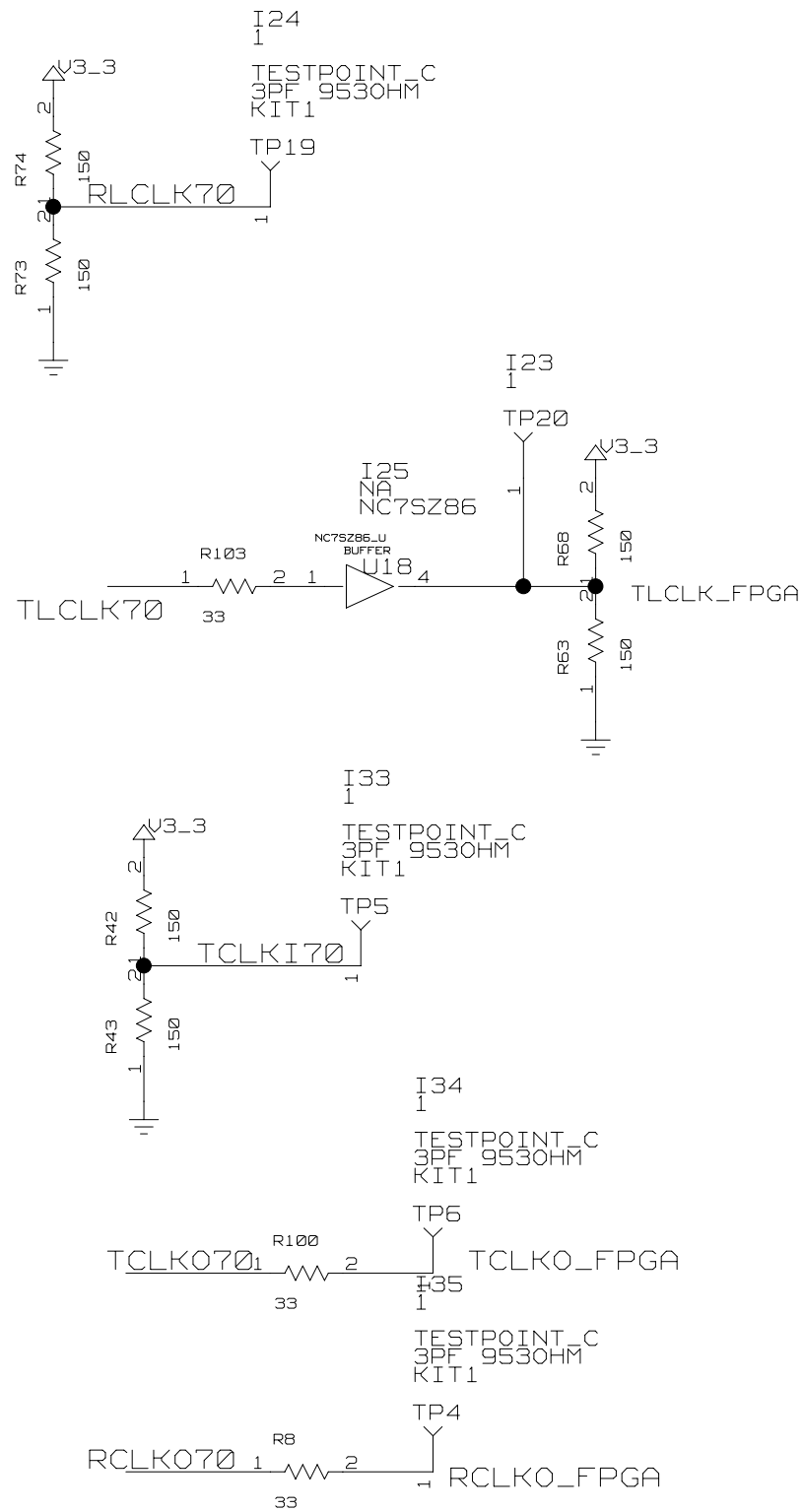
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3

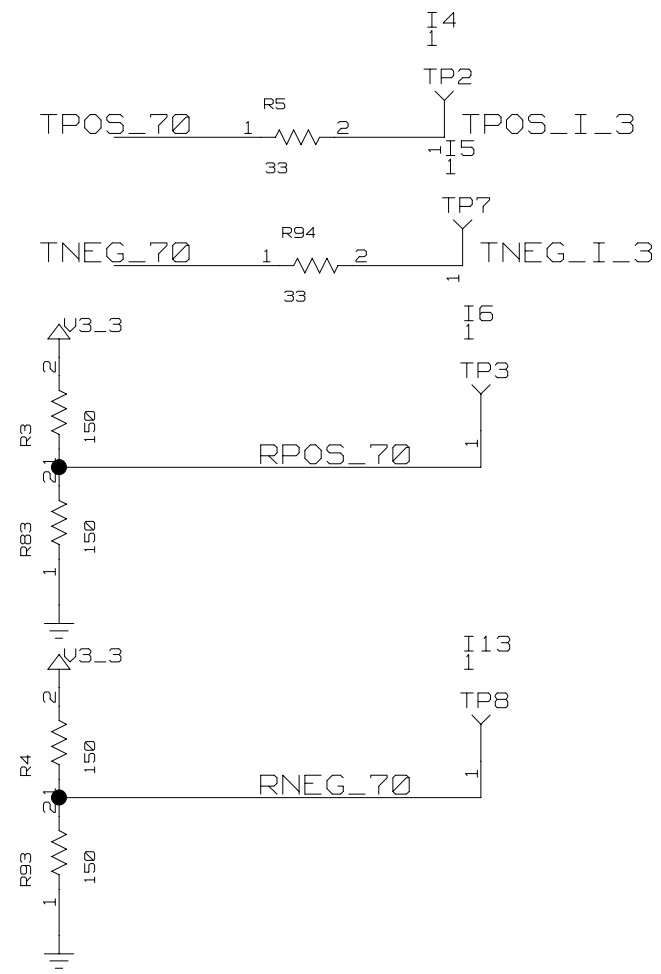
2

1

# TCLK/RCLK TERMINATION

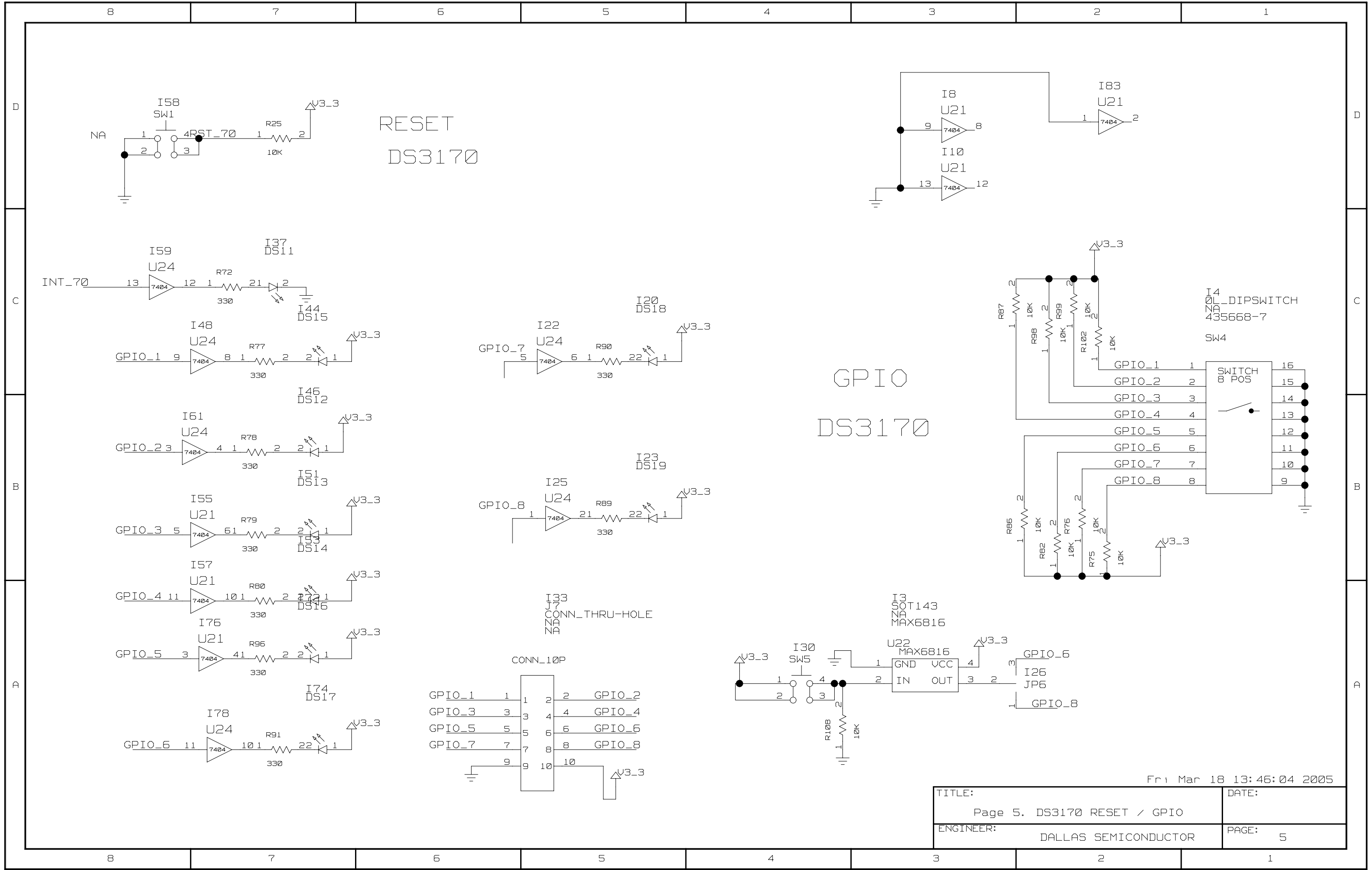


# TELECOM DATA IO TPOS/TNEG/RPOS/RNEG



Fri Mar 18 13:46:04 2005

TITLE: Page 4. TCLK/RCLK/TELECOM DATA	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 4



RESET  
DS3170

GPIO  
DS3170

Fri Mar 18 13:46:04 2005

TITLE:	Page 5. DS3170 RESET / GPIO	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	5

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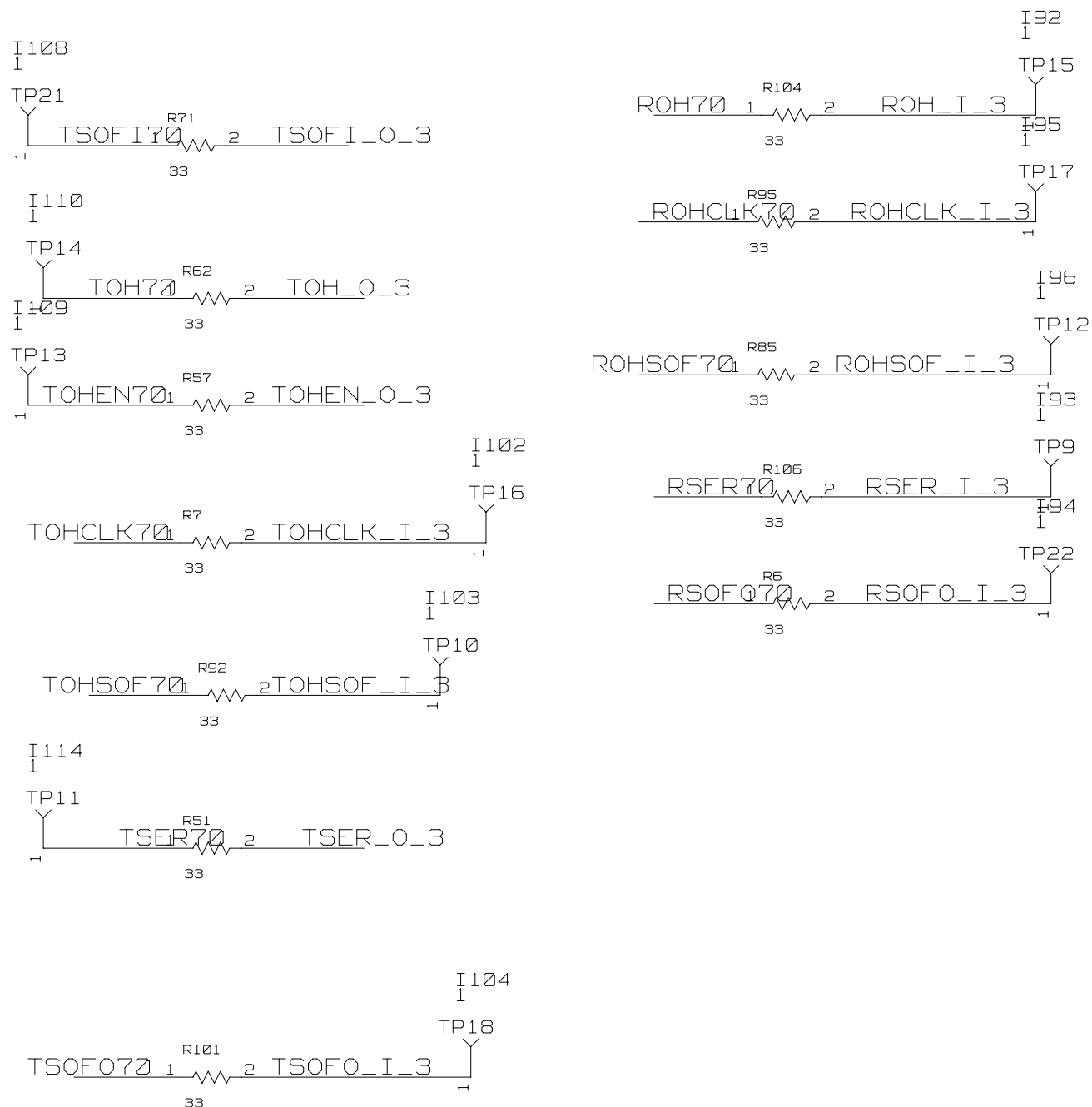
1

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D

# DS3170

## MISC TELECOM TERM



Fri Mar 18 13:46:05 2005

TITLE:	Page 6. MISC TELECOM SIGNALS	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	6

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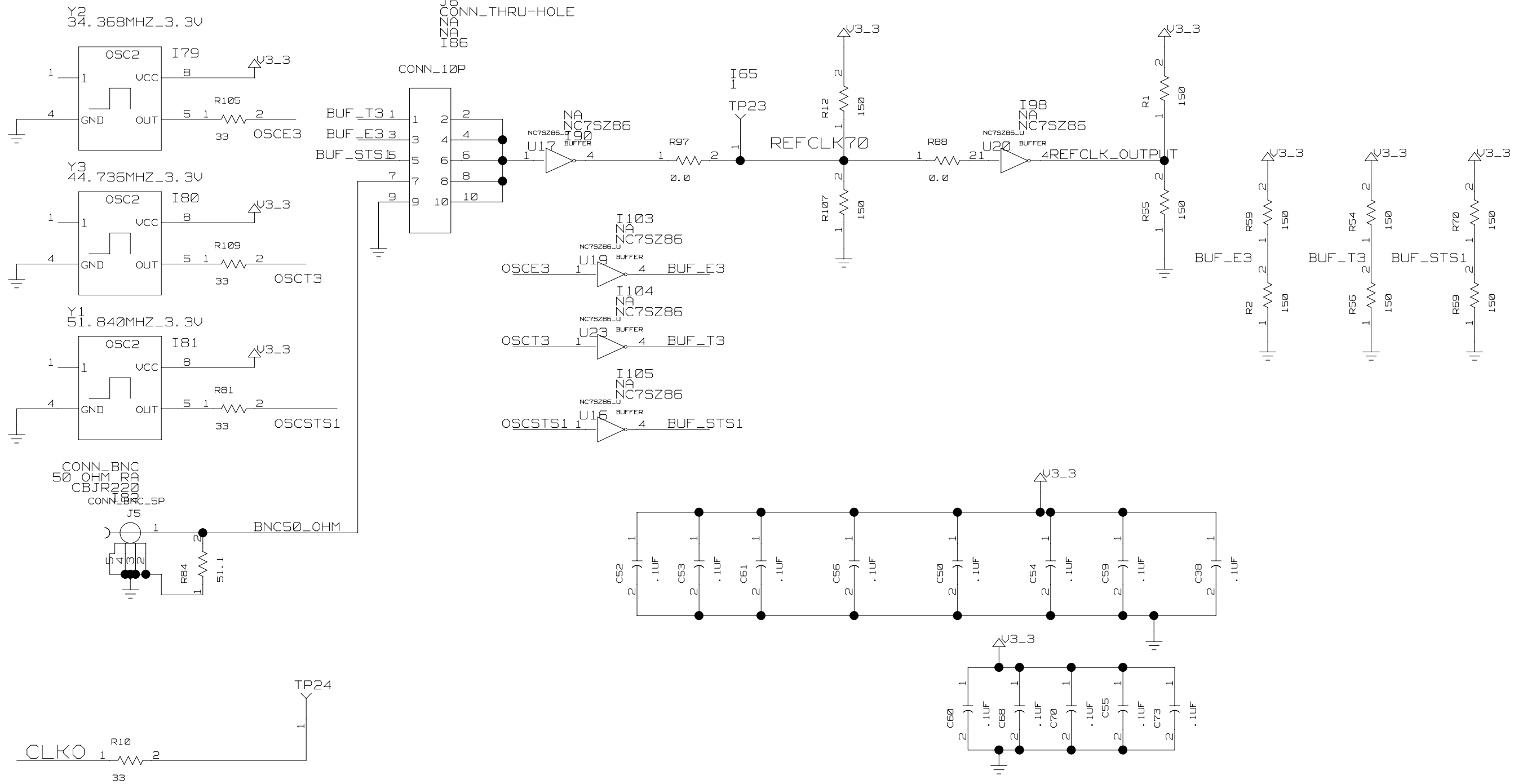
2

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A

A

# REFERENCE CLOCK

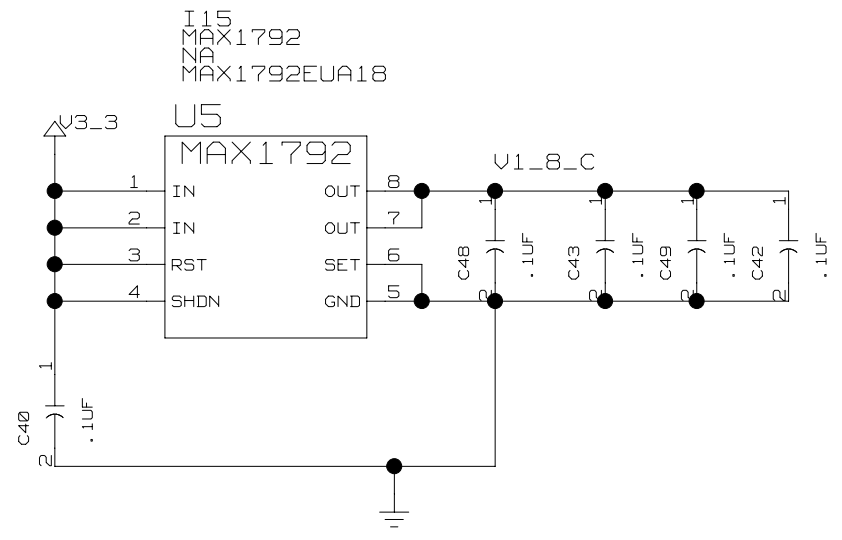


Fri Mar 18 13:46:05 2005

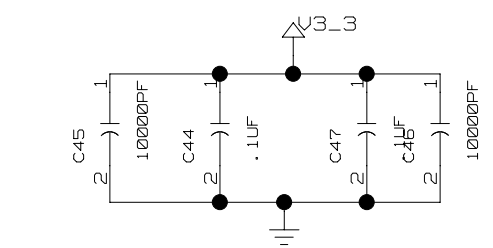
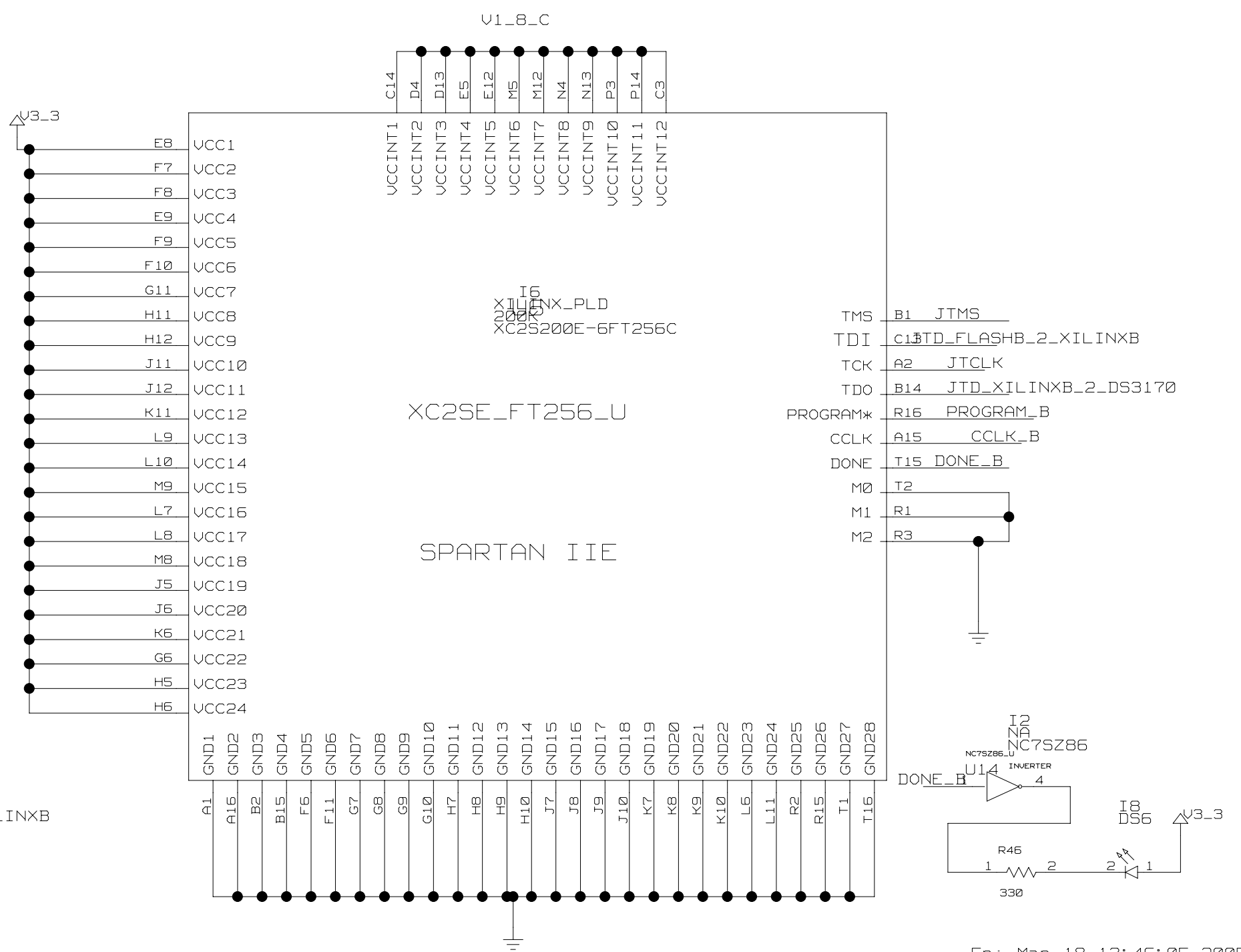
TITLE: Page 7. REF OSC	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 7



8 7 6 5 4 3 2 1



### FPGA PORT <DS3170>

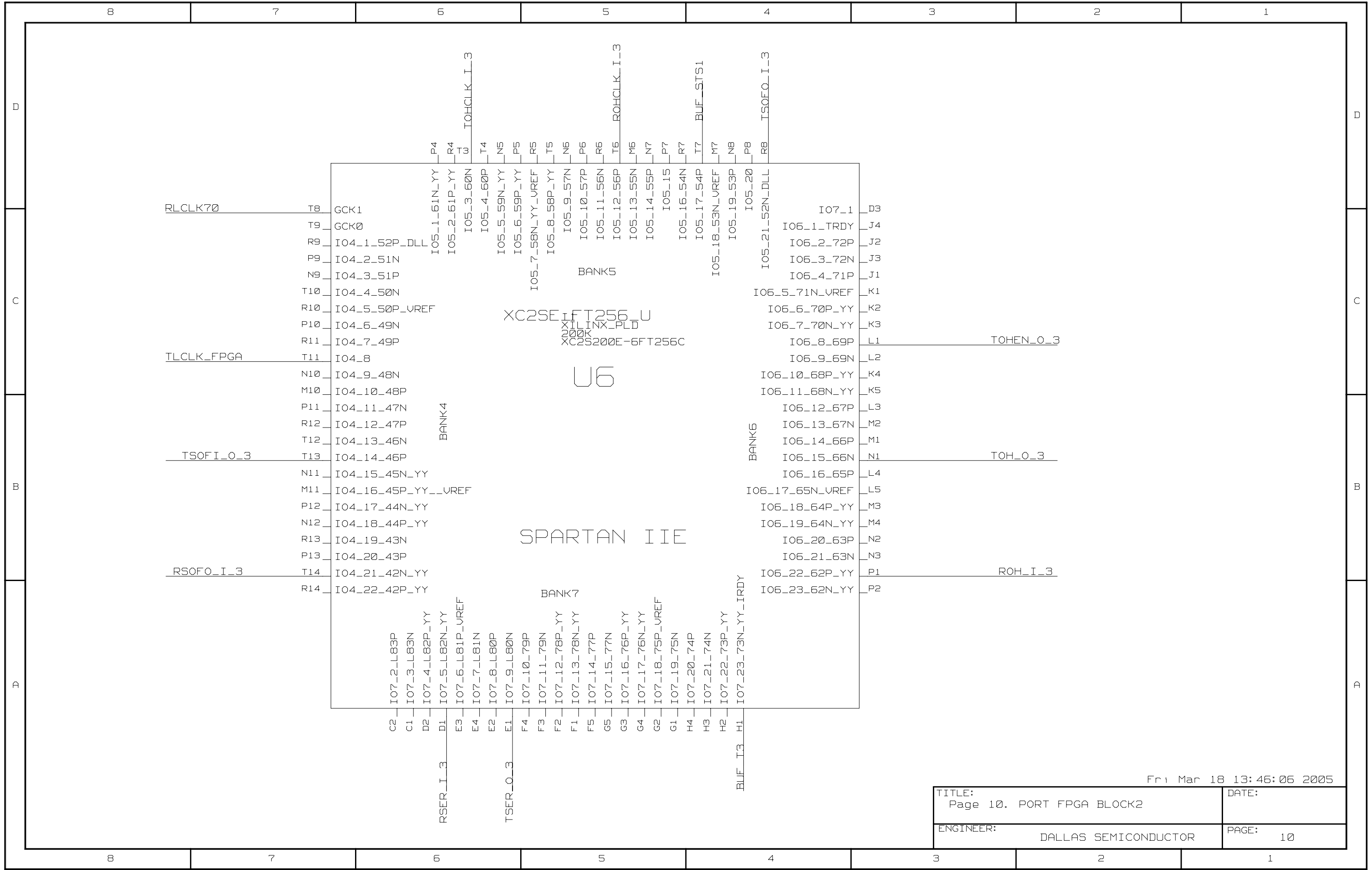


Fri Mar 18 13:46:05 2005

TITLE: Page 8. PORT FPGA CONTROL / FLASH	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 8

8 7 6 5 4 3 2 1



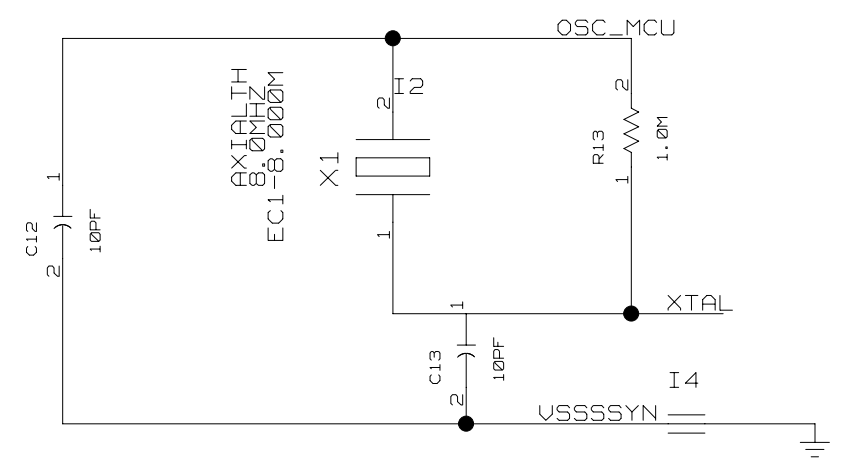
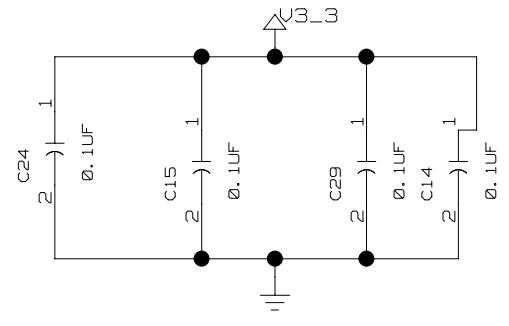
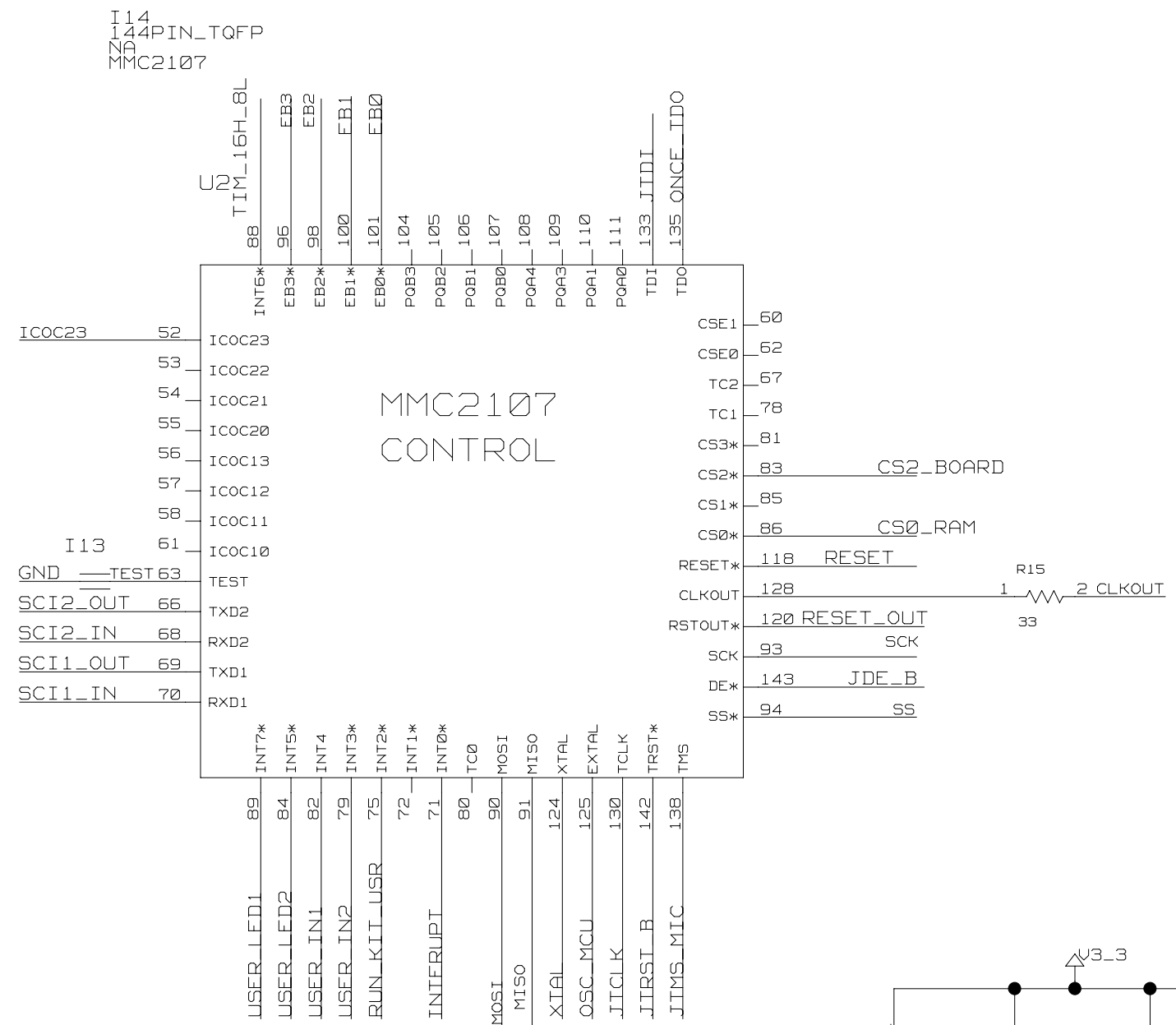


XC2SE1FT256\_U  
 XC2S200E-6FT256C

SPARTAN IIE

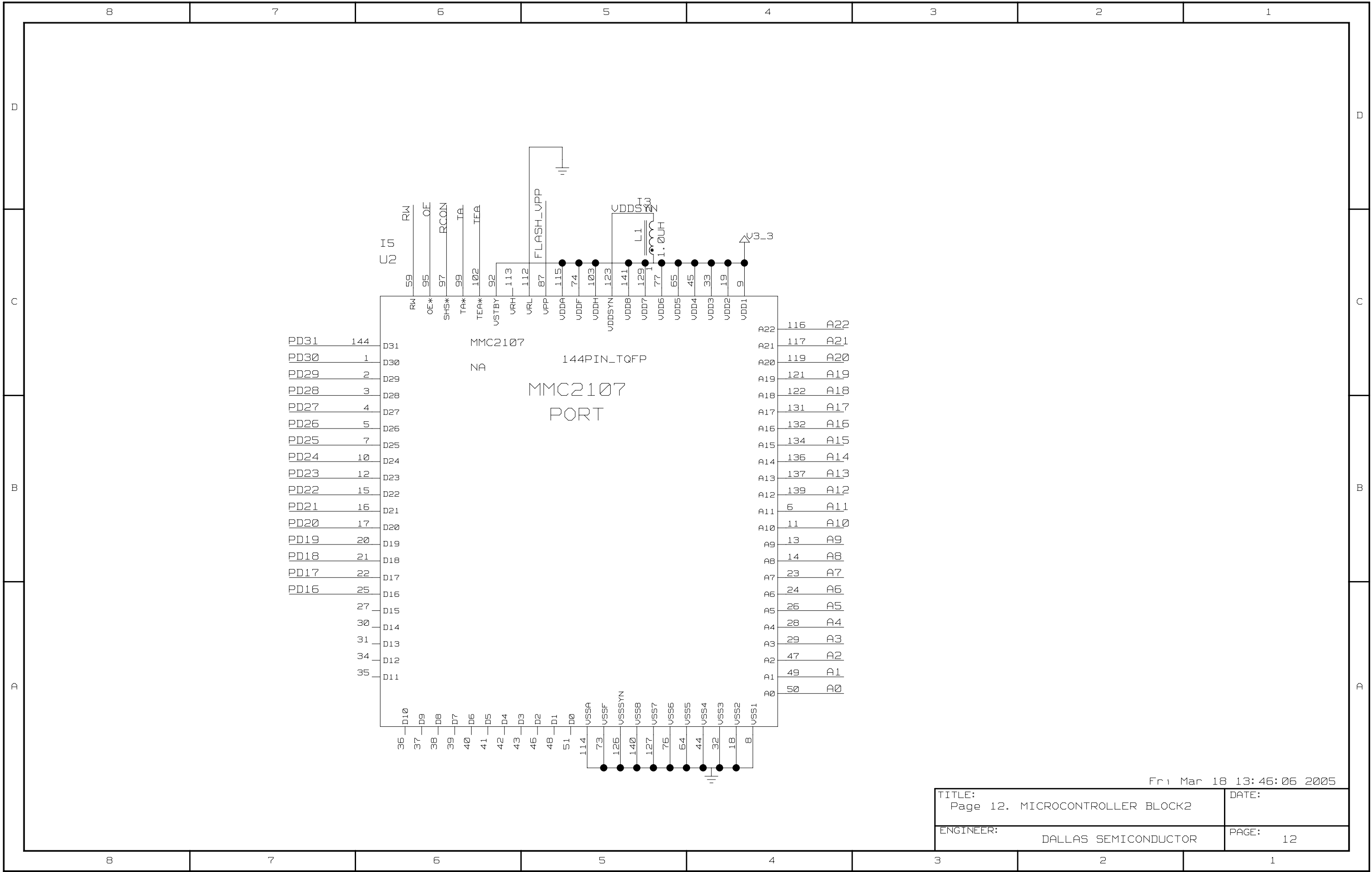
Fri Mar 18 13:46:06 2005

TITLE: Page 10. PORT FPGA BLOCK2	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 10



Fri Mar 18 13:46:06 2005

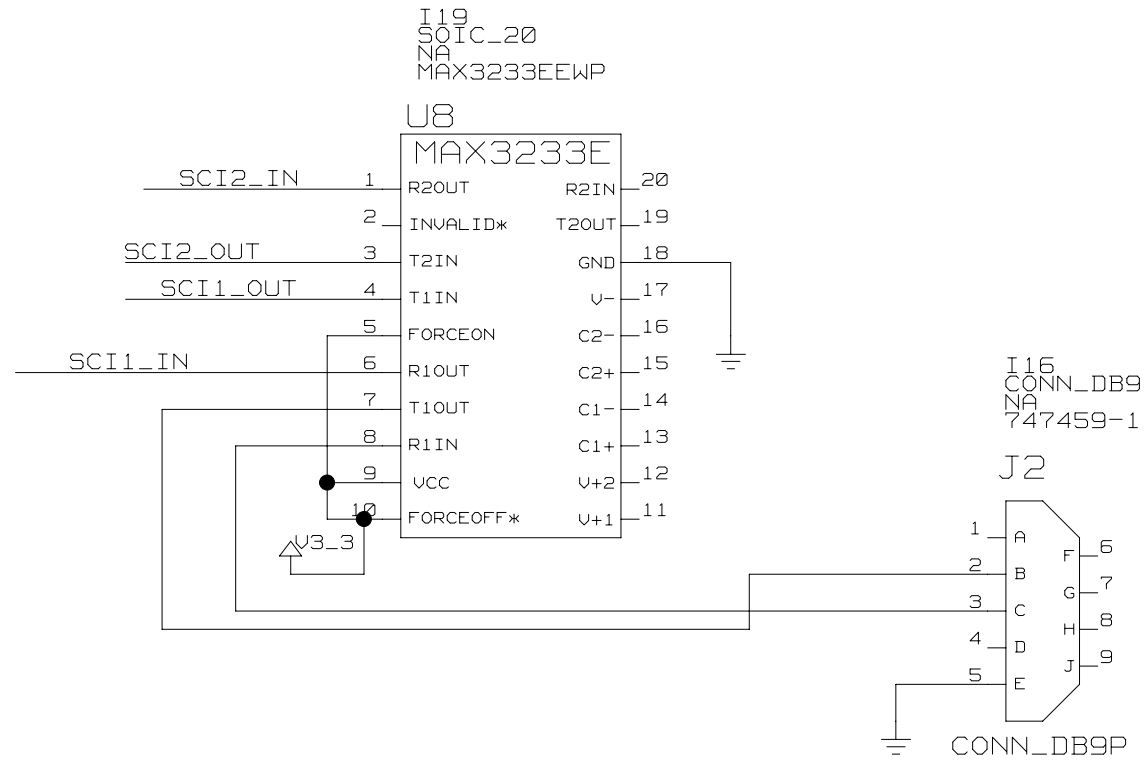
TITLE: Page 11. MICROCONTROLLER BLOCK1	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 11



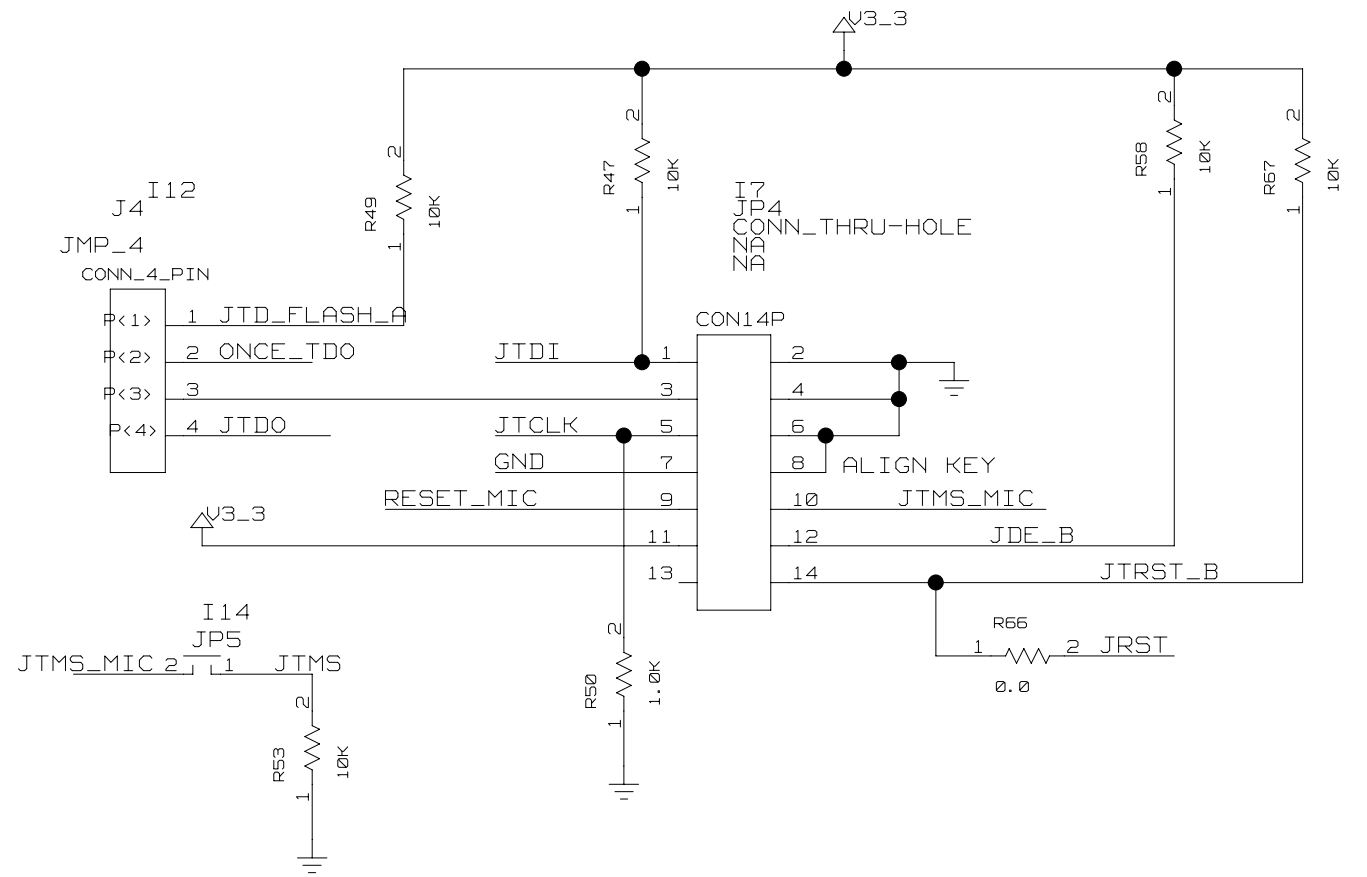
Fri Mar 18 13:46:06 2005

TITLE: Page 12. MICROCONTROLLER BLOCK2	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 12

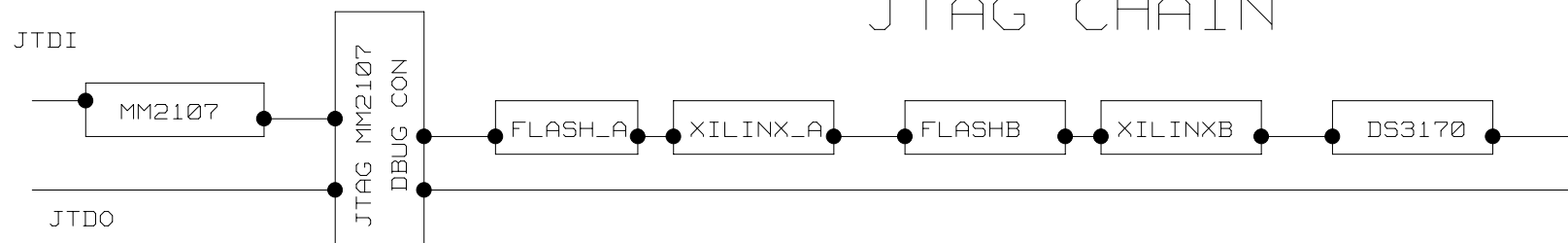
# SERIAL INTERFACE



# JTAG CON



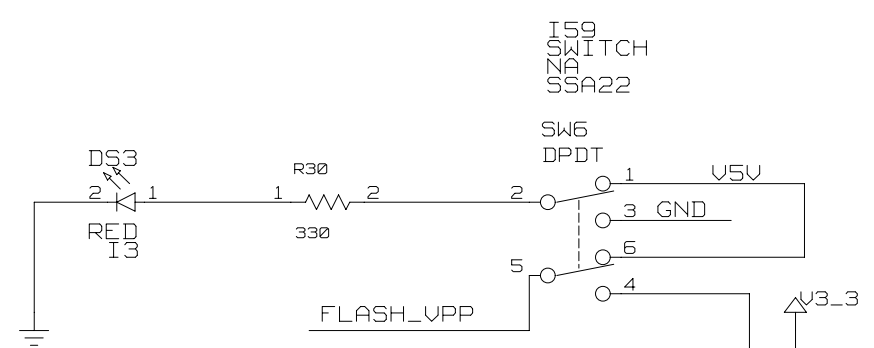
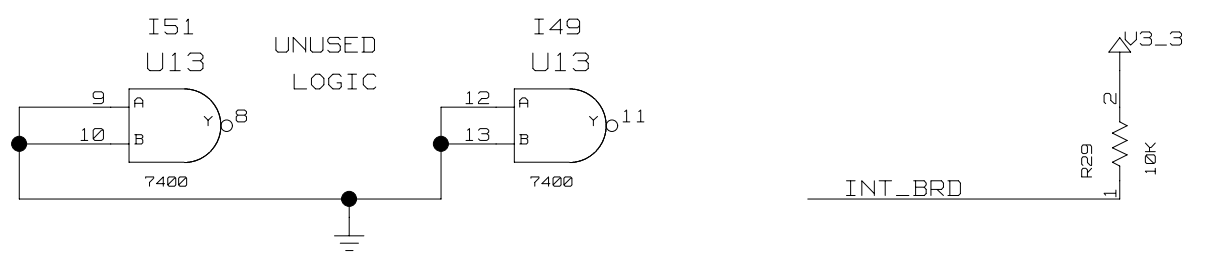
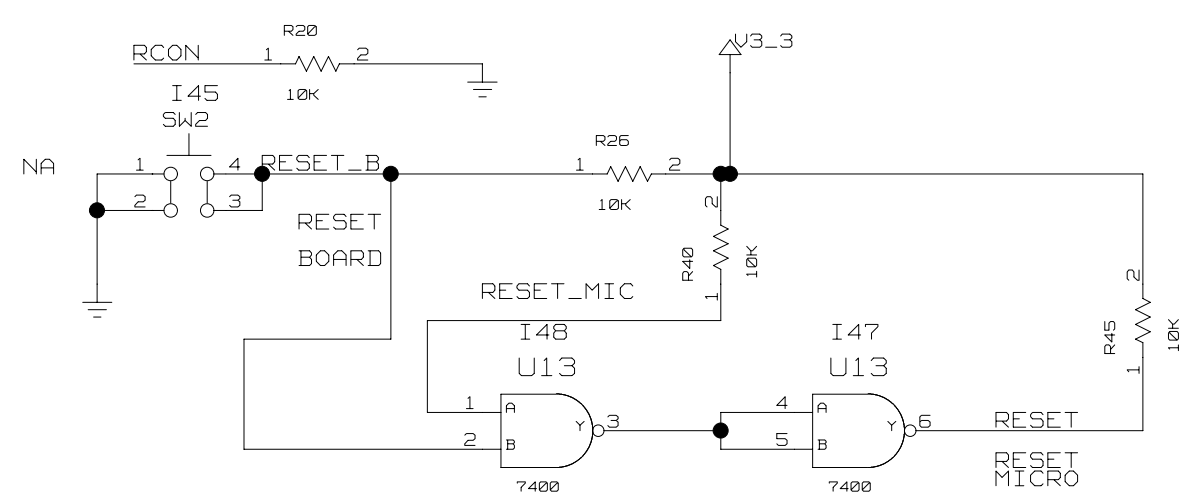
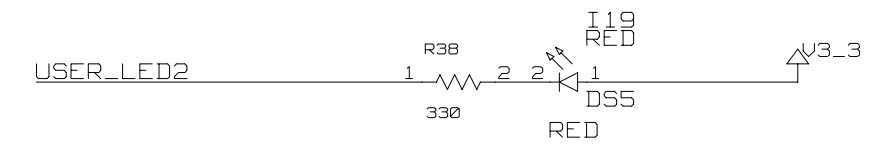
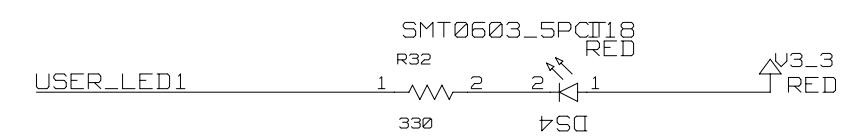
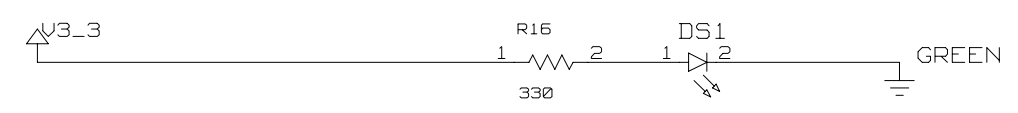
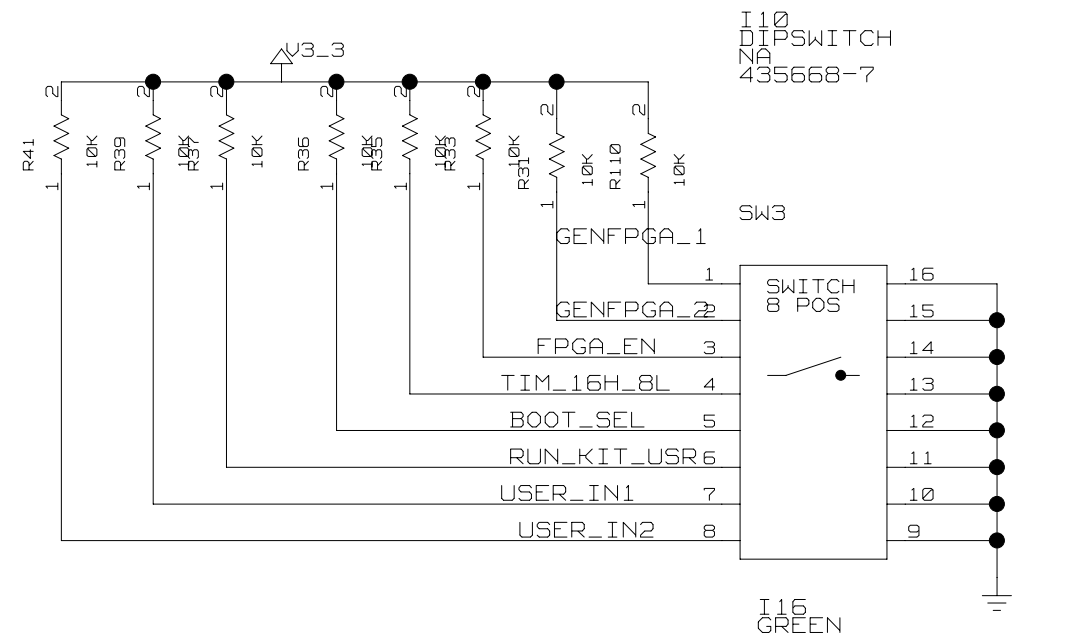
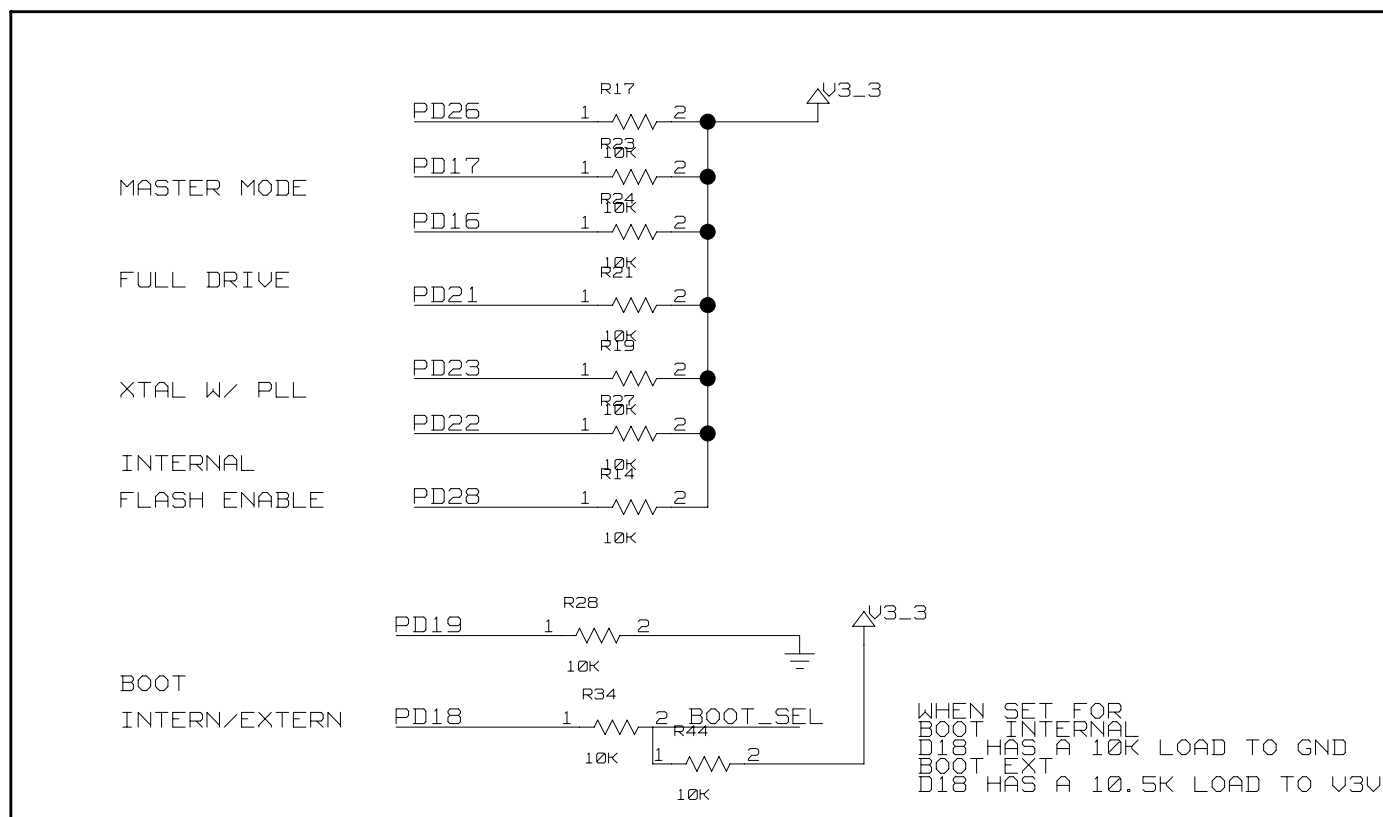
# JTAG CHAIN



Fri Mar 18 13:46:06 2005

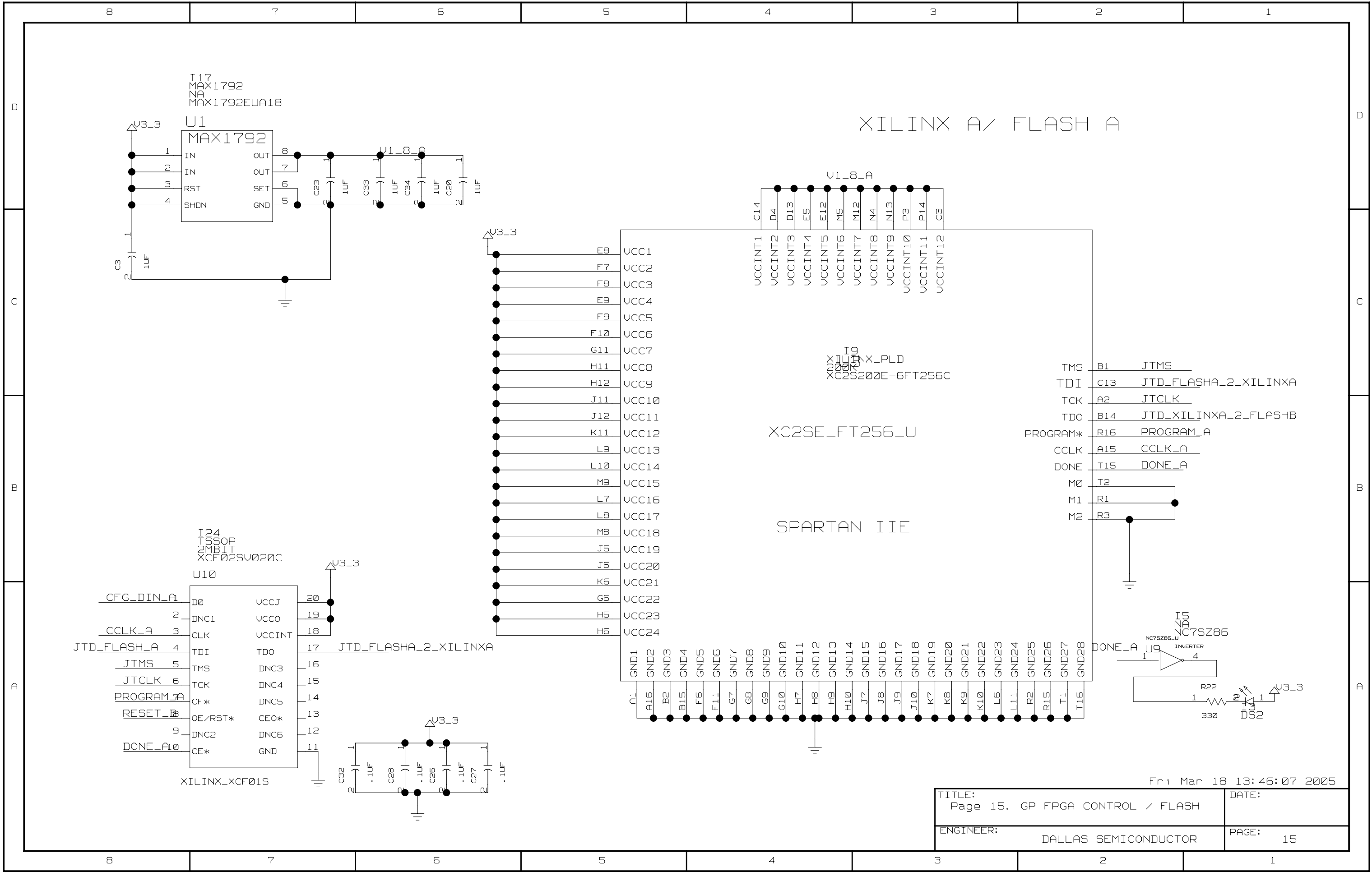
TITLE: Page 13. SERIAL/JTAG CONN	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 13

# RESET CONFIGURATION



Fri Mar 18 13:46:07 2005

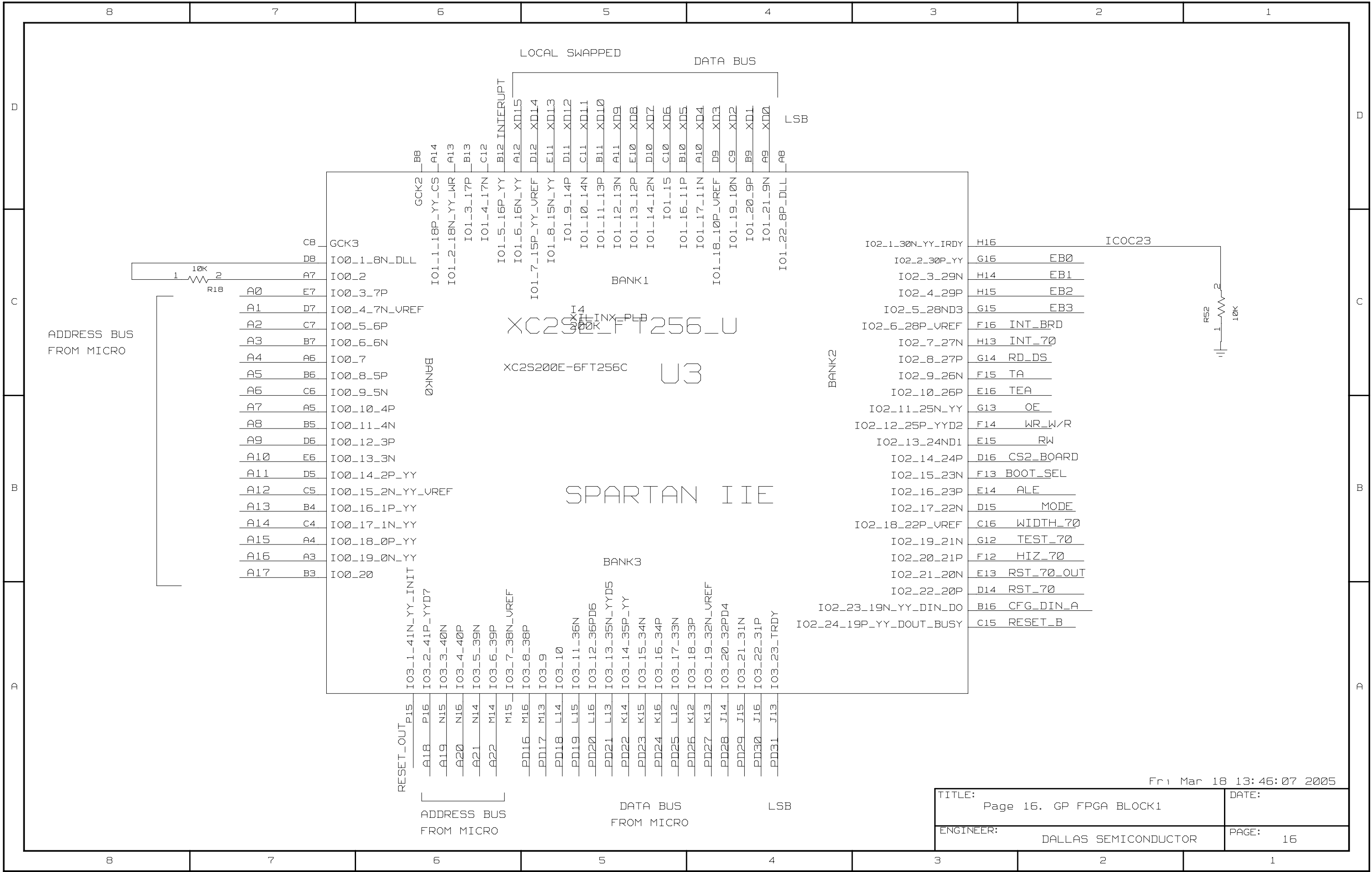
TITLE:	Page 14. MISC USER INPUTS	DATE:
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE: 14



Fri Mar 18 13:46:07 2005

TITLE: Page 15. GP FPGA CONTROL / FLASH	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 15



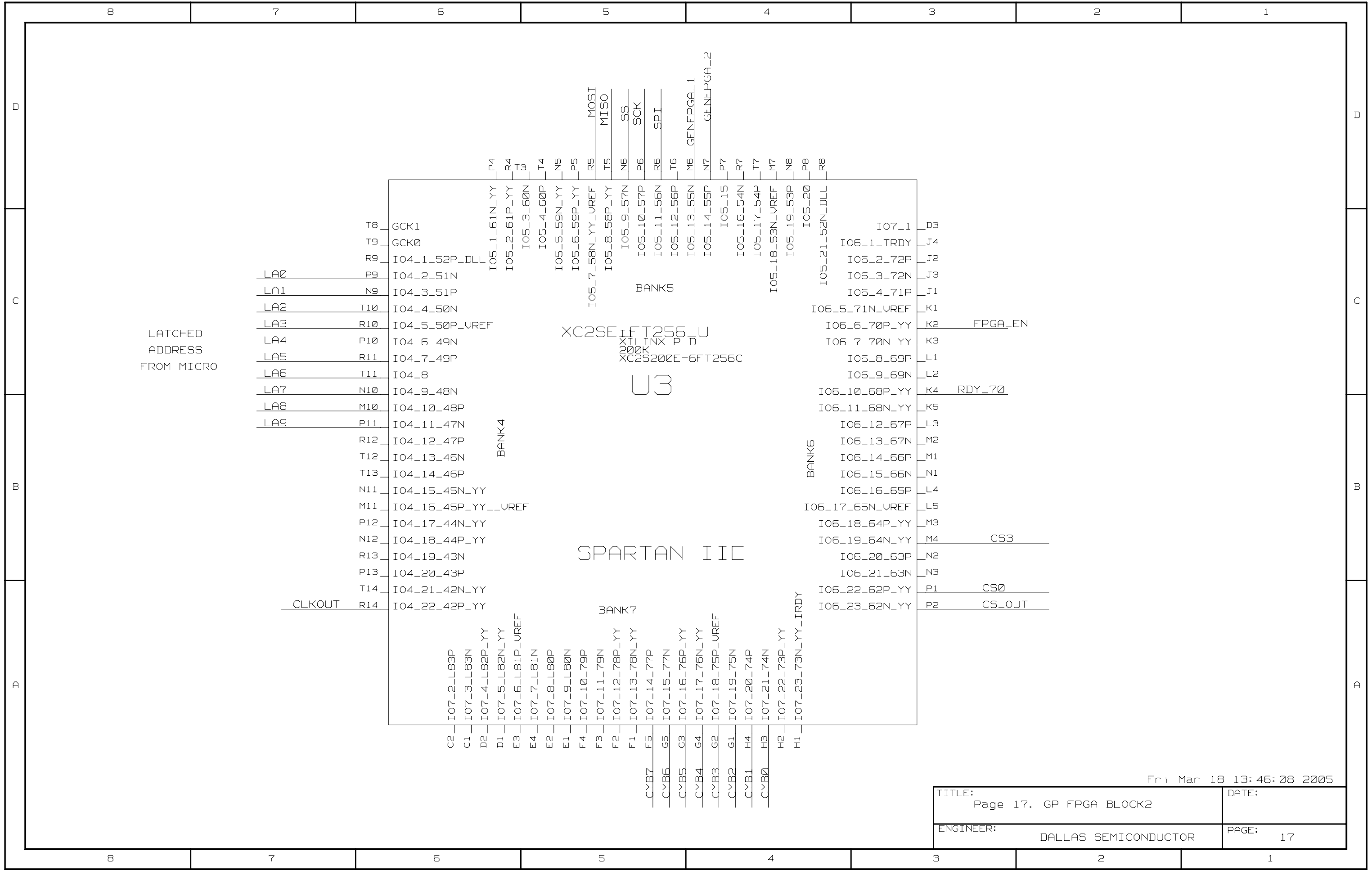


SPARTAN IIE

XC2S200E-6FT256C U3

Fri Mar 18 13:46:07 2005

TITLE: Page 16. GP FPGA BLOCK1	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 16



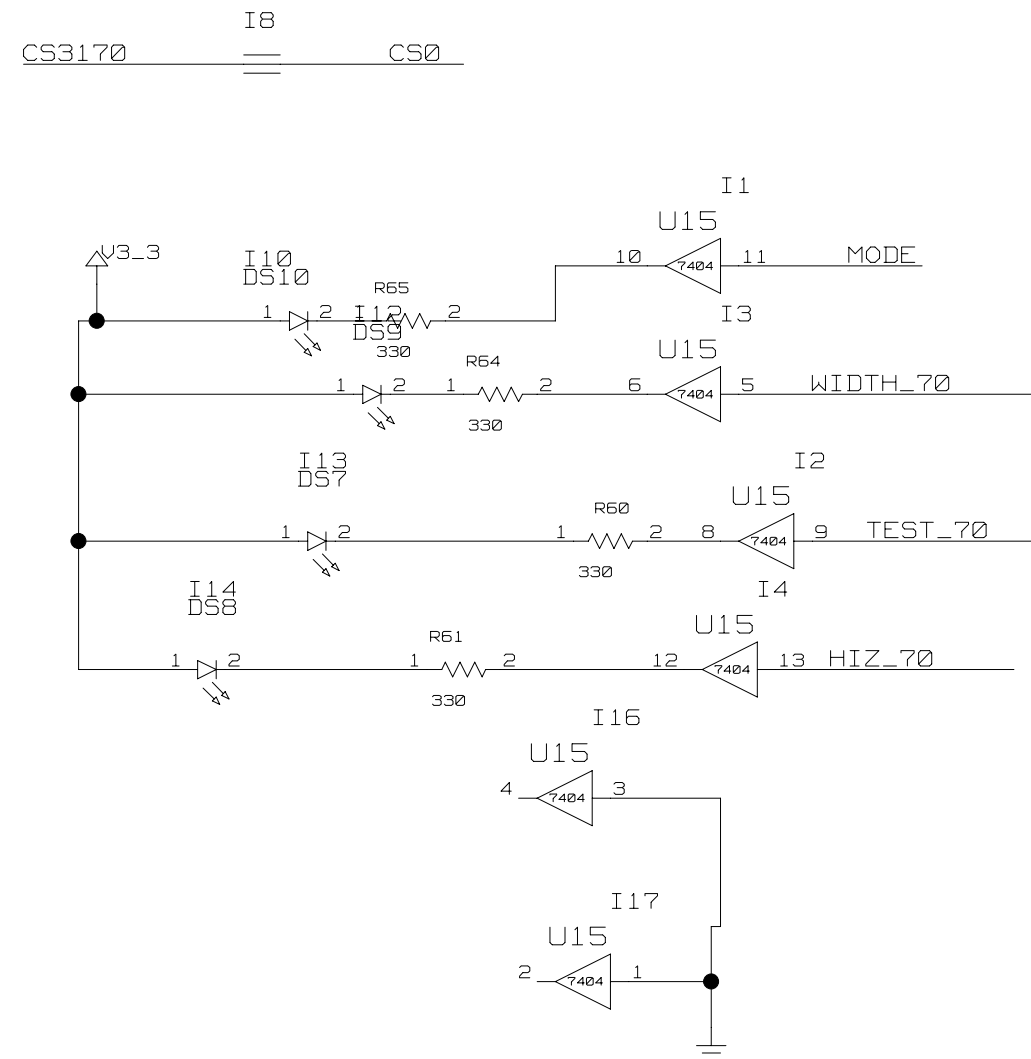
Fri Mar 18 13:46:08 2005

TITLE: Page 17. GP FPGA BLOCK2	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 17

I18  
 J3  
 0L\_THROUGH HOLE  
 NA  
 TSW-125-07-T-D

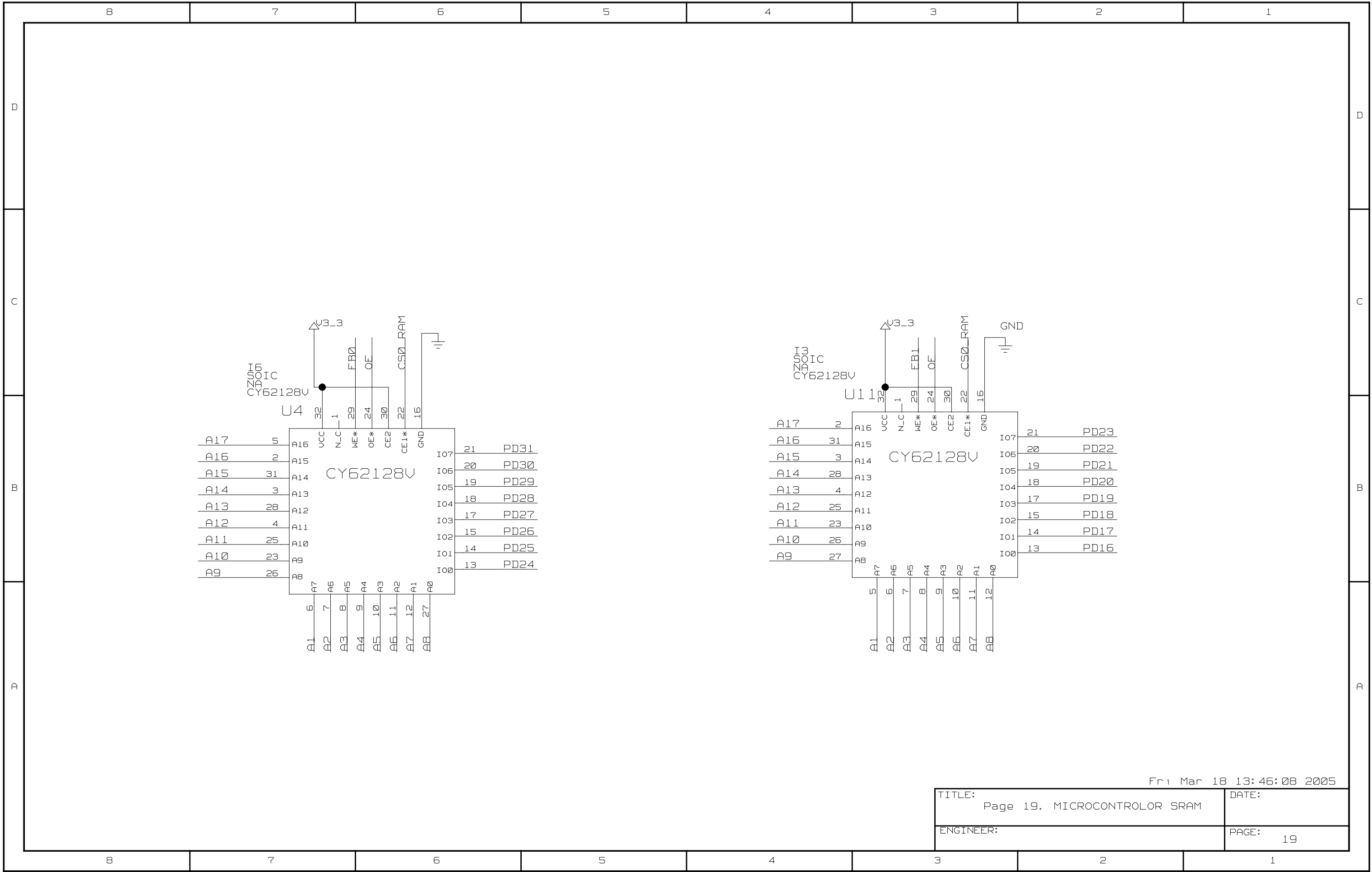
MISC HEADERS

LA0	1	1	2	2	XD0
LA1	3	3	4	4	XD1
LA2	5	5	6	6	XD2
LA3	7	7	8	8	XD3
LA4	9	9	10	10	XD4
LA5	11	11	12	12	XD5
LA6	13	13	14	14	XD6
LA7	15	15	16	16	XD7
LA8	17	17	18	18	XD8
LA9	19	19	20	20	XD9
CS3170	21	21	22	22	XD10
CS3	23	23	24	24	XD11
INT_70	25	25	26	26	XD12
RST_70_OUT	27	27	28	28	XD13
RDY_70	29	29	30	30	XD14
CYB0	31	31	32	32	XD15
CYB1	33	33	34	34	SPI
CYB2	35	35	36	36	ALE
CYB3	37	37	38	38	RD_DS
CYB4	39	39	40	40	WR_W/R
CYB5	41	41	42	42	CS_OUT
CYB6	43	43	44	44	MODE
CYB7	45	45	46	46	WIDTH_70
GND	47	47	48	48	TEST_70
GND	49	49	50	50	HIZ_70



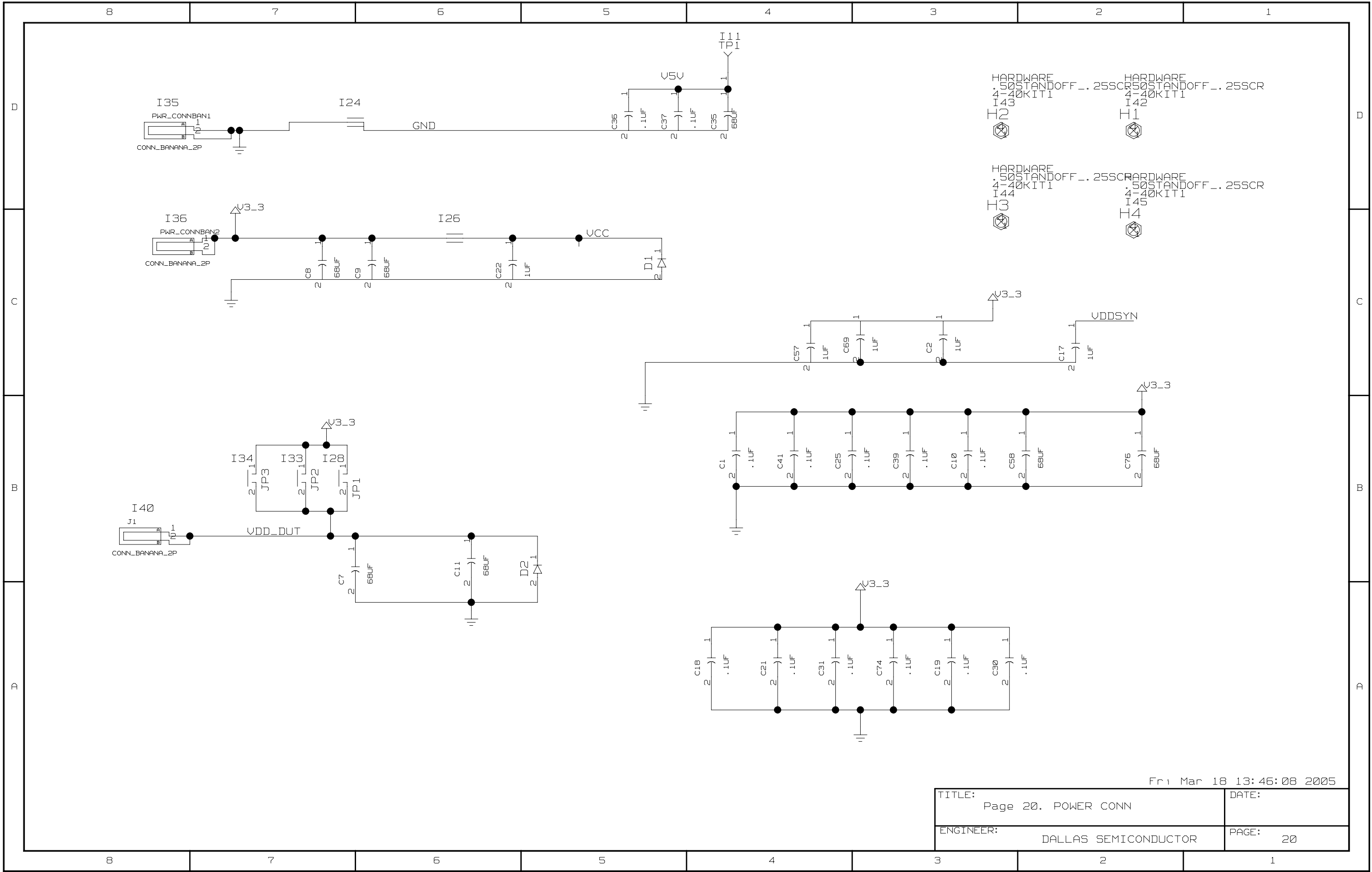
Fri Mar 18 13:46:08 2005

TITLE:	Page 18. ADDRESS/DATA HEADERS	DATE:
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE: 18



Fri Mar 18 13:46:08 2005

TITLE: Page 19. MICROCONTROLOR SRAM	DATE:
ENGINEER:	PAGE: 19



HARDWARE  
 .50STANDOFF..25SCR  
 4-40KIT1  
 I43  
 H2

HARDWARE  
 .50STANDOFF..25SCR  
 4-40KIT1  
 I42  
 H1

HARDWARE  
 .50STANDOFF..25SCR  
 4-40KIT1  
 I44  
 H3

HARDWARE  
 .50STANDOFF..25SCR  
 4-40KIT1  
 I45  
 H4

Fri Mar 18 13:46:08 2005

TITLE: Page 20. POWER CONN	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 20

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DESIGN NOTES:

1. 1/20/05 DESIGN / LAYOUT COMPLETED AND ARCHIEVED

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Fri Mar 18 13:46:09 2005

TITLE: Page 21. NOTES	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 21

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	8	7	6	5	4	3	2	1	
D	*** Signal Cross-Reference for the entire design ***								
	A0	12A4<> 16C7<>	JTCLK	8A8<> 11A6<> 13C3<> 15A8<> 2D5<> 8C2<> 15B1<>	RUN_KIT_USR	11A7<> 14C3<>			
	A1	12A4<> 16C7<> 19A3<> 19A7<>	JTDI	11C6<> 13C3<>	RW	12D6<> 16B2<>			
A2	12A4<> 16C7<> 19A3<> 19A7<>	JTDO	2D5<> 13C4<>	RXN_70	2C2<> 3A4<>				
A3	12A4<> 16C7<> 19A3<> 19A7<>	JTD_FLASHA_2_XILINXA	15A6<> 15C1<>	RXP_70	2C2<> 3A4<>				
A4	12A4<> 16C7<> 19A3<> 19A6<>	JTD_FLASHB_2_XILINXB	8A6<> 8C2<>	SC11_IN	11B8<> 13C8<>				
A5	12A4<> 16C7<> 19A3<> 19A6<>	JTD_FLASH_A	15A8<> 13C4<>	SC11_OUT	11B8<> 13C8<>				
A6	12A4<> 16B7<> 19A3<> 19A6<>	JTD_XILINXA_2_FLASHB	8A8<> 15B1<>	SC12_IN	11B8<> 13C8<>				
A7	12B4<> 16B7<> 19A3<> 19A6<>	JTD_XILINXB_2_DS3170	8B2<> 2D5<>	SC12_OUT	11B8<> 13C8<>				
A8	12B4<> 16B7<> 19A3<> 19A6<>	JTMS	8A8<> 8C2<> 13B4<> 15A8<> 15C1<> 2D5<>	SCK	11B5<> 17D5<>				
A9	12B4<> 16B7<> 19B4<> 19B7<>	JTMS_MIC	11A6<> 13B4<> 13C2<>	SPI	17D5<> 18B6<> 2A6<>				
A10	12B4<> 16B7<> 19B4<> 19B7<>	JTRST_B	11A6<> 13B2<>	SS	11B5<> 17D5<>				
A11	12B4<> 16B7<> 19B4<> 19B7<>	LA0	9C7<> 17C7<> 18C8<> 2C7<>	TA	12D6<> 16C2<>				
A12	12B4<> 16B7<> 19B4<> 19B7<>	LA1	9C7<> 17C7<> 18C8<> 2C7<>	TCLKI70	4B7<> 9D4<> 2B2<>				
A13	12B4<> 16B7<> 19B4<> 19B7<>	LA2	9C7<> 17C7<> 18C8<> 2C7<>	TCLK070	2B2<> 4A7<>				
A14	12B4<> 16B7<> 19B4<> 19B7<>	LA3	9B7<> 17C7<> 18C8<> 2C7<>	TCLK0_FPGA	4A6<> 9C7<>				
A15	12B4<> 16B7<> 19B4<> 19B7<>	LA4	9B7<> 17C7<> 18C8<> 2C7<>	TEA	12D6<> 16B2<>				
A16	12B4<> 16B7<> 19B4<> 19B7<>	LA5	9B7<> 17C7<> 18C8<> 2C7<>	TEST	11B8<>				
A17	12B4<> 16B7<> 19B4<> 19B7<>	LA6	9B7<> 17C7<> 18C8<> 2C7<>	TEST_70	16B2<> 18A6<> 2A3<> 18B2<>				
A18	12B4<> 16A6<>	LA7	9B7<> 17C7<> 18C8<> 2C7<>	TIM_16H_8L	11C7<> 14C3<>				
A19	12C4<> 16A6<>	LA8	9B7<> 17B7<> 18C8<> 2C7<>	TLCLK70	2C2<> 4C7<>				
A20	12C4<> 16A6<>	LA9	9B7<> 17B7<> 18B8<>	TLCLK_FPGA	4B6<> 10C8<>				
A21	12C4<> 16A6<>	MISO	11A6<> 17D5<>	TNEG_70	2C2<> 4B4<>				
A22	12C4<> 16A6<>	MODE	9B2<> 16B2<> 18A6<> 2A6<> 18B3<>	TNEG_I_3	4B3<> 9D6<>				
ALE	9C2<> 16B2<> 18B6<> 2D6<>	MOSI	11A6<> 17D5<>	TOH70	6C7<> 2B2<>				
BNC50_OHM	7B7<>	OE	12D6<> 16B2<> 19C3<> 19C6<>	TOHCLK70	2B2<> 6B7<>				
BOOT_SEL	14C3<> 16B2<> 14B6<>	ONCE_TDO	11C6<> 13C4<>	TOHCLK_I_3	6B6<> 10D6<>				
BUF_E3	7C5<> 7C6<> 9A5<> 7C2<>	OSCE3	7C6<> 7C7<>	TOHEN70	6C7<> 2B2<>				
BUF_ST51	7B5<> 7C6<> 10D4<> 7C1<>	OSCE3	7C6<> 7C7<>	TOHEN_O_3	10C2<> 6C6<>				
BUF_T3	7C5<> 7C6<> 10A4<> 7C2<>	OSCE3	7C6<> 7C7<>	TOHSOF70	2B2<> 6B7<>				
CCLK_A	15A8<> 15B1<>	OSCE3	7C6<> 7C7<>	TOHSOF_I_3	6B6<> 9B2<>				
CCLK_B	8A8<> 8B1<>	OSC_MCU	11A6<> 11C2<>	TOH_O_3	10B2<> 6C6<>				
CFG_DIN_A	15A8<> 16A2<>	PD16	12A7<> 16A5<> 19B2<> 14D7<>	TPOS_70	2C2<> 4C4<>				
CFG_DIN_B	8A8<> 9A2<>	PD17	12B7<> 16A5<> 19B2<> 14D7<>	TPOS_I_3	4C3<> 9A7<>				
CLKO	2D4<> 7A8<>	PD18	12B7<> 16A5<> 19B2<> 14B7<>	TSER70	6A7<> 2B2<>				
CLKOUT	17A7<> 11B4<>	PD19	12B7<> 16A5<> 19B2<> 14C7<>	TSER_O_3	10A6<> 6A6<>				
CS0	17A2<> 18C4<>	PD20	12B7<> 16A5<> 19B2<>	TSOFI70	6C7<> 2B2<>				
CS0_RAM	11B5<> 19C3<> 19C6<>	PD21	12B7<> 16A5<> 19B2<> 14C7<>	TSOFI_O_3	10B8<> 6C6<>				
CS2_BOARD	11B5<> 16B2<>	PD22	12B7<> 16A5<> 19B2<> 14C7<>	TSOFI70	2A2<> 6A7<>				
CS3	9C2<> 17B2<> 18B8<>	PD23	12B7<> 16A5<> 19B2<> 14C7<>	TXN_70	2C3<> 3C4<>				
CS3170	18B8<> 2D6<> 18C5<>	PD24	12B7<> 16A5<> 19B5<>	TXP_70	2C3<> 3C4<>				
CS_OUT	17A2<> 18B6<>	PD25	12B7<> 16A5<> 19B5<>	USER_IN1	11A7<> 14C3<>				
CYB0	9B2<> 17A4<> 18B8<>	PD26	12B7<> 16A4<> 19B5<> 14D7<>	USER_IN2	11A7<> 14C3<>				
CYB1	9B2<> 17A4<> 18B8<>	PD27	12B7<> 16A4<> 19B5<>	USER_LED1	11A7<> 14B3<>				
CYB2	9B2<> 17A4<> 18B8<>	PD28	12B7<> 16A4<> 19B5<> 14C7<>	USER_LED2	11A7<> 14B3<>				
CYB3	9B2<> 17A4<> 18B8<>	PD29	12C7<> 16A4<> 19B5<>	V1_8_A	15D6<> 15D4<>				
CYB4	9B2<> 17A4<> 18B8<>	PD30	12C7<> 16A4<> 19B5<>	V1_8_C	8D7<> 8D4<>				
CYB5	9A2<> 17A5<> 18B8<>	PD31	12C7<> 16A4<> 19B5<>	V5U	14A2<> 20D5<>				
CYB6	9A2<> 17A5<> 18A8<>	PROGRAM_A	15A8<> 15B1<>	UDDSYN	12C5<> 20C2<>				
CYB7	9A2<> 17A5<> 18A8<>	PROGRAM_B	8A8<> 8B1<>	UDD_DUT	20B7<> 2B2<> 2B8<> 2C8<> 2D5<> 11C2<>				
DONE_A	15A2<> 15A8<> 15B1<>	RCLK070	2A2<> 4A7<>	USSSSYN	11C2<>				
DONE_B	8A2<> 8A8<> 8B2<>	RCLK0_FPGA	4A6<> 9D6<>	WIDTH_70	16B2<> 18A6<> 2A6<> 18B2<>				
EB0	11C7<> 16C2<> 19C7<>	RCON	12D6<> 14B8<>	WR_W/R	9C2<> 16B2<> 18B6<> 2D6<>				
EB1	11C7<> 16C2<> 19C3<>	RDY_70	2A6<> 17B3<> 18B8<>	XD0	2C7<> 9D5<> 16D4<> 18C6<>				
EB2	11C7<> 16C2<>	RD_DS	9B2<> 16C2<> 18B6<> 2D6<>	XD1	2B7<> 9D5<> 16D4<> 18C6<>				
EB3	11C7<> 16C2<>	REFCLK70	7C4<> 2D4<>	XD2	2B7<> 9D5<> 16D4<> 18C6<>				
FLASH_VPP	14A3<> 12D5<>	REFCLK_OUTPUT	7C3<> 9A4<>	XD3	2B7<> 9D5<> 16D4<> 18C6<>				
FPGA_EN	14D3<> 17C3<>	RESET	11B5<> 14A5<>	XD4	2B7<> 9D5<> 16D4<> 18C6<>				
GENFPGA_1	14D3<> 17D4<>	RESET_B	8A8<> 9A2<> 9B2<> 14B7<> 15A8<> 16A2<>	XD5	2B7<> 9D5<> 16D5<> 18C6<>				
GENFPGA_2	14D3<> 17D4<>	RESET_MIC	13C3<> 14A7<>	XD6	2B7<> 9D5<> 16D5<> 18C6<>				
GPIO_1	2A4<> 5A6<> 5C2<> 5C8<>	RESET_OUT	11B5<> 16A6<>	XD7	2B7<> 9D5<> 16D5<> 18C6<>				
GPIO_2	2A4<> 5A5<> 5C2<> 5B8<>	RLCLK70	4C7<> 2C2<> 10C8<>	XD8	2B7<> 16D5<> 18C6<>				
GPIO_3	2A4<> 5A6<> 5B2<> 5B8<>	RNEG_70	4A3<> 9D6<> 2C2<>	XD9	2B7<> 16D5<> 18B6<>				
GPIO_4	2A4<> 5A5<> 5B2<> 5A8<>	ROH70	2B2<> 6C5<>	XD10	2B7<> 16D5<> 18B6<>				
GPIO_5	2A4<> 5A6<> 5B2<> 5A8<>	ROHCLK70	2B2<> 6C5<>	XD11	2B7<> 16D5<> 18B6<>				
GPIO_6	2A4<> 5A2<> 5A5<> 5B2<> 5A8<>	ROHCLK_I_3	6C4<> 10D5<>	XD12	2B7<> 16D5<> 18B6<>				
GPIO_7	2A4<> 5A6<> 5B2<> 5C6<>	ROHSOF70	2B2<> 6C5<>	XD13	2A7<> 16D5<> 18B6<>				
GPIO_8	2A4<> 5A2<> 5A5<> 5B2<> 5B6<>	ROHSOF_I_3	6C4<> 9C2<>	XD14	2A7<> 16D5<> 18B6<>				
HIZ_70	16B2<> 18A6<> 2A3<> 18B2<>	ROH_I_3	6C4<> 10B2<>	XD15	2A7<> 16D6<> 18B6<>				
ICOC23	11C8<> 16C2<>	RPOS_70	4B3<> 9B7<> 2C2<>	XTAL	11A6<> 11C2<>				
INTERUPT	11A7<> 16D6<>	RSER70	2A2<> 6B5<>						
INT_70	2A6<> 16C2<> 18B8<> 5C8<>	RSER_I_3	6B4<> 10A6<>						
INT_BRD	9A7<> 16C2<> 14A6<>	RSOF070	2A2<> 6B5<>						
JDE_B	11B5<> 13C2<>	RSOF0_I_3	6B4<> 10B8<>						
JRST	2D5<> 13B1<>	RST_70	5D8<> 16A2<>						
		RST_70_OUT	16B2<> 18B8<> 2A3<>						
C									
B									
A									
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						ENGINEER:		PAGE:	

